Notice for TAIYO YUDEN Products

Please read this notice before using the TAIYO YUDEN products.

REMINDERS

Product information in this catalog is as of October 2018. All of the contents specified herein are subject to change without notice due to technical improvements, etc. Therefore, please check for the latest information carefully before practical application or use of our products.

Please note that TAIYO YUDEN shall not be in any way responsible for any damages and defects in products or equipment incorporating our products, which are caused under the conditions other than those specified in this catalog or individual product specification sheets.

- Please contact TAIYO YUDEN for further details of product specifications as the individual product specification sheets are available.
- Please conduct validation and verification of our products in actual condition of mounting and operating environment before using our products.
- The products listed in this catalog are intended for use in general electronic equipment (e.g., AV equipment, OA equipment, home electric appliances, office equipment, information and communication equipment including, without limitation, mobile phone, and PC) and medical equipment classified as Class I or II by IMDRF. Please be sure to contact TAIYO YUDEN for further information before using the products for any equipment which may directly cause loss of human life or bodily injury (e.g., transportation equipment including, without limitation, automotive powertrain control system, train control system, and ship control system, traffic signal equipment, disaster prevention equipment, medical equipment classified as Class III by IMDRF, highly public information network equipment including, without limitation, telephone exchange, and base station).

Please do not incorporate our products into any equipment requiring high levels of safety and/or reliability (e.g., aerospace equipment, aviation equipment*, medical equipment classified as Class IV by IMDRF, nuclear control equipment, undersea equipment, military equipment).

*Note: There is a possibility that our products can be used only for aviation equipment that does not directly affect the safe operation of aircraft (e.g., in-flight entertainment, cabin light, electric seat, cooking equipment) if such use meets requirements specified separately by TAIYO YUDEN. Please be sure to contact TAIYO YUDEN for further information before using our products for such aviation equipment.

When our products are used even for high safety and/or reliability-required devices or circuits of general electronic equipment, it is strongly recommended to perform a thorough safety evaluation prior to use of our products and to install a protection circuit as necessary.

Please note that unless you obtain prior written consent of TAIYO YUDEN, TAIYO YUDEN shall not be in any way responsible for any damages incurred by you or third parties arising from use of the products listed in this catalog for any equipment requiring inquiry to TAIYO YUDEN or prohibited for use by TAIYO YUDEN as described above.

- Information contained in this catalog is intended to convey examples of typical performances and/or applications of our products and is not intended to make any warranty with respect to the intellectual property rights or any other related rights of TAIYO YUDEN or any third parties nor grant any license under such rights.
- Please note that the scope of warranty for our products is limited to the delivered our products themselves and TAIYO YUDEN shall not be in any way responsible for any damages resulting from a fault or defect in our products. Notwithstanding the foregoing, if there is a written agreement (e.g., supply and purchase agreement, quality assurance agreement) signed by TAIYO YUDEN and your company, TAIYO YUDEN will warrant our products in accordance with such agreement.
- The contents of this catalog are applicable to our products which are purchased from our sales offices or authorized distributors (hereinafter "TAIYO YUDEN's official sales channel"). Please note that the contents of this catalog are not applicable to our products purchased from any seller other than TAIYO YUDEN's official sales channel.
- Caution for Export
 Some of our products listed in this catalog may require specific procedures for export according to "U.S. Export
 Administration Regulations", "Foreign Exchange and Foreign Trade Control Law" of Japan, and other applicable
 regulations. Should you have any questions on this matter, please contact our sales staff.

MULTILAYER CERAMIC CAPACITORS



WAVE

REFLOW

■PARTS NUMBER

J	М	Κ	3	1	6	Δ	В	J	1	0	6	М	L	_	Т	Δ
1	2	3		4		⑤	(6		7		8	9	10	11	12

△=Blank space

 $\textcircled{1} \mathsf{Rated} \ \mathsf{voltage}$

Code	Rated voltage[VDC]
Р	2.5
Α	4
J	6.3
L	10
E	16
Т	25
G	35
U	50
Н	100
Q	250
S	630
Х	2000

3End terminatio	n
Code	End termination
K	Plated
S	Cu Internal Electrodes (For High Frequency)

4 Dimension (L × W)

Туре	Dimensions (L×W)[mm]	EIA (inch)
021	0.25 × 0.125	008004
042	0.4 × 0.2	01005
063	0.6 × 0.3	0201
105	1.0 × 0.5	0402
105	0.52 × 1.0 💥	0204
107	1.6 × 0.8	0603
107	0.8 × 1.6 💥	0306
212	2.0 × 1.25	0805
212	1.25 × 2.0 💥	0508
316	3.2 × 1.6	1206
325	3.2 × 2.5	1210
432	4.5 × 3.2	1812

Note: ※LW reverse type(□WK) only

②Series name

Code	Series name
М	Multilayer ceramic capacitor
V	Multilayer ceramic capacitor for high frequency
W	LW reverse type multilayer capacitor

⑤Dimension tolerance

Code	Туре	L[mm]	W[mm]	T[mm]
Δ	ALL	Standard	Standard	Standard
	063	0.6±0.05	0.3±0.05	0.3±0.05
	105	1.0±0.10	0.5±0.10	0.5±0.10
	107	1.6+0.15/-0.05	0.8+0.15/-0.05	0.8+0.15/-0.05
				0.45 ± 0.05
Α	212	2.0+0.15/-0.05	1.25 + 0.15 / -0.05	0.85±0.10
				1.25 + 0.15 / -0.05
	316	3.2±0.20	1.6±0.20	0.85±0.10
	310	3.2±0.20	1.6±0.20	1.6±0.20
	325	3.2±0.30	2.5±0.30	2.5±0.30
	063	0.6 ± 0.09	0.3±0.09	0.3±0.09
	105	1.0+0.15/-0.05	0.5+0.15/-0.05	0.5+0.15/-0.05
	107	1.6+0.20/-0	0.8+0.20/-0	0.45 ± 0.05
В	107	1.0+0.20/ -0	0.8 + 0.20/ - 0	0.8+0.20/-0
Ь				0.45±0.05
	212	2.0+0.20/-0	1.25 + 0.20 / -0	0.85±0.10
				1.25 + 0.20 / -0
	316	3.2 ± 0.30	1.6±0.30	1.6±0.30
С	105	1.0+0.20/-0	0.5+0.20/-0	0.5+0.20/-0
E	105	1.0+0.30/-0	0.5+0.30/-0	0.5+0.30/-0

Note: cf. STANDARD EXTERNAL DIMENSIONS

Δ= Blank space

(6)Temperature characteristics code

■ High dielectric type (Excluding Super low distortion multilayer ceramic capacitor)

Code	Applicable standard		Temperature range[°C]	Ref. Temp.[°C]	Capacitance change	Capacitance tolerance	Tolerance code										
	JIS	В	-25 ~ + 85	20	±10%	±10%	K										
BJ	013	ь	25.9 1 65	20	± 10 %	±20%	М										
ы	EIA	X5R	-55 ~ + 85	25	±15%	±10%	K										
	EIA	YOK	-55~+ 85	25	<u> </u>	±20%	М										
B7	EIA	X7R	-55 ~ +125	25	±15%	±10%	K										
Б/	EIA	X/IX	33.9 T 123	2.5	± 13 70	±20%	М										
C6	EIA X6S	Vec	VEC	VEC	VGC	VGC	VEC	Vec	Vec	VEC	VAS	VAS	-55 ~ +105	25	±22%	±10%	K
		703	-55°₹ ± 105	25	± 22%	±20%	М										
C7	ΕΙΛ	X7S	-55 ~ +125	0.5	±220/	±10%	K										
G/	EIA	EIA X/S	-55~+125	25	±22%	±20%	М										
1.5(%)					F14 V5D	FF 0F	0.5	1.450/	±10%	K							
LD(※)	EIA	X5R	−55~+ 85	25	±15%	±20%	М										

Note: X.LD Low distortion high value multilayer ceramic capacitor

Δ= Blank space

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our product specification sheets. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/).

■Temperature compensating type

Code	Applicable standard		Temperature range[°C]	Ref. Temp.[°C]	Capacitance change	Capacitance tolerance	Tolerance code
				25		±0.05pF	Α
	EIA	COG	−55∼+125			±0.1pF	В
CG					0±30ppm/°C	±0.25pF	С
						±0.5pF	D
						±5%	J
	JIS	S UJ		20	−750±120ppm/°C	±0.25pF	С
UJ			$-55 \sim +125$			±0.5pF	D
	EIA	U2J		25		±5%	J
UK	JIS	UK	−55~+125	20	-750±250ppm/°C	±0.25pF	С
UK	EIA	U2K	−55~ +125	25	—/30±230ppIII/ C	±0.23pr	C
SL	JIS	SL	-55 ~ +125	20	+350~-1000ppm/°C	±5%	J

6 Series code

·Super low distortion multilayer ceramic capacitor

Super low distortion matchager ceramic capacitor					
Code	Series code				
SD	Standard				

•Medium-High Voltage Multilayer Ceramic Capacitor

Code	Series code
SD	Standard

7Nominal capacitance

©11011111111 04P401141100						
Code (example)	Nominal capacitance					
0R5	0.5pF					
010	1pF					
100	10pF					
101	100pF					
102	1,000pF					
103	10,000pF					
104	0.1 μ F					
105	1.0 <i>μ</i> F					
106	10 μ F					
107	100 μ F					

Note: R=Decimal point

8 Capacitance tolerance

O Capacitance to	Dictance
Code	Capacitance tolerance
Α	±0.05pF
В	±0.1pF
С	±0.25pF
D	±0.5pF
F	±1pF
G	±2%
J	±5%
K	±10%
М	±20%
Z	+80/-20%

Thickness

Code	Thickness[mm]
K	0.125
Н	0.13
E	0.18
С	0.2
D	0.2
Р	0.3
Т	0.3
K	0.45(107type or more)
V	0.5
W	0.3
Α	0.8
D	0.85(212type or more)
F	1.15
G	1.25
L	1.6
N	1.9
Υ	2.0 max
М	2.5

10Special code

Code	Special code
_	Standard

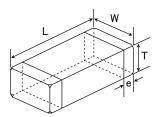
11)Packaging

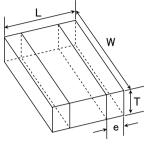
Code	Packaging							
F	<i>ϕ</i> 178mm Taping (2mm pitch)							
Т	ϕ 178mm Taping (4mm pitch)							
В	ϕ 178mm Taping (4mm pitch, 1000 pcs/reel)							
Р	325 type (Thickness code M)							
R	ϕ 178mm Taping (2mm pitch)105type only							
К	(Thickness code E,H)							
W	ϕ 178mm Taping(1mm pitch)021/042type only							

12Internal code

9	
Code	Internal code
Δ	Standard

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our product specification sheets. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/).





LW reverse type

Type(EIA)			imension [mm]				
Type(En()	L	W	Т	*1	е		
□MK021 (008004)	0.25±0.013	0.125±0.013	0.125 ± 0.013	K	0.0675 ± 0.0275		
□VS021 (008004)	0.25±0.013	0.125±0.013	0.125 ± 0.013	K	0.0675 ± 0.0275		
□MK042(01005)	0.4±0.02	0.2±0.02	0.2±0.02	C D	0.1±0.03		
□VS042(01005)	0.4±0.02	0.2±0.02	0.2±0.02	С	0.1±0.03		
				Р	0.45.4.0.05		
□MK063(0201)	0.6±0.03	0.3±0.03	0.3 ± 0.03	Т	0.15±0.05		
			0.13±0.02	Н			
			0.18±0.02	Е			
☐MK105(0402)	1.0±0.05	0.5 ± 0.05	0.2 ± 0.02	С	0.25 ± 0.10		
			0.3±0.03	Р			
			0.5±0.05	٧			
□VK105(0402)	1.0±0.05	0.5±0.05	0.5±0.05	W	0.25±0.10		
□WK105(0204)※	0.52±0.05	1.0±0.05	0.3±0.05	Р	0.18±0.08		
DMK107(0600)	16+010	0.8±0.10	0.45±0.05	K	0.25 ± 0.25		
□MK107(0603)	1.6±0.10	0.8±0.10	0.8±0.10	Α	0.35±0.25		
□WK107(0306)※	0.8±0.10	1.6±0.10	0.5±0.05	٧	0.25±0.15		
			0.45±0.05	K			
□MK212(0805)	2.0±0.10	1.25±0.10	0.85±0.10	D	0.5 ± 0.25		
			1.25±0.10	G			
□WK212(0508)※	1.25±0.15	2.0±0.15	0.85±0.10	D	0.3±0.2		
			0.85±0.10	D			
□MK316(1206)	3.2±0.15	1.6±0.15	1.15±0.10	F	0.5 + 0.35 / -0.25		
			1.6±0.20	L			
			0.85±0.10	D			
			1.15±0.10	F			
□MK325(1210)	3.2±0.30	2.5±0.20	1.9±0.20	N	0.6 ± 0.3		
			1.9+0.1/-0.2	Υ			
			2.5±0.20	М			
	45.10.40	001000	2.0+0/-0.30	Υ	0.6±0.4		
□MK432(1812)	4.5±0.40	3.2±0.30	2.5±0.20	М	0.9±0.6		

Note: X. LW reverse type, *1.Thickness code

■STANDARD QUANTITY

т	EIA (inch)	Dime	nsion	Standard o	uantity[pcs]		
Type	EIA (inch)	[mm]	Code	Paper tape	Embossed tape		
021	008004	0.125	K	_	50000		
040	01005	0.2	С		40000		
042	01005	0.2	D	_	40000		
063	0201	0.3	Р	15000			
003	0201	0.3	T	15000	_		
		0.13	Н	_	Embossed tap 50000 40000		
		0.18	E	_	15000		
	0400	0.2	С	20000	_		
105	0402	0.3	Р	15000	_		
		٥٢	V	20000 — 15000 — 10000 — 4000 —			
		0.5	W		_		
	0204 ※	0.30	Р		Embossed tape 50000 40000 20000 15000 4000 3000 3000 3000 2000		
	0000	0.45	K	4000	Embossed tape 50000 40000 20000 15000 4000 3000 3000 3000 2000 2000		
107	0603	0.8	Α	4000			
	0306 ※	0.50	V	_	4000		
		0.45	K	4000			
040	0805	0.85	D	4000	_		
212		1.25	G	_	3000		
	0508 ※	0.85	D	4000	_		
		0.85	D	4000	_		
316	1206	1.15	F	-	3000		
		1.6	L	_	2000		
		0.85	D				
		1.15	F		2000		
325	1210	1.9	N	_	2000		
		2.0 max	Υ				
		2.5	М	-	1000		
400	1010	2.0 max	Υ	-	1000		
432	1812	2.5	М	_	500		

Note : ※.LW Reverse type(□WK)

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our product specification sheets. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/).

Multilayer Ceramic Capacitors (Temperature compensating type)

021TYPF

[Temperature Characteristic CG : CG/C0G($-55 \sim +125 ^{\circ}$ C)] 0.125mm thickness(K)

Temperature Charac	cteristic CG : CG/C	0G(−55~-	F125℃)] 0.12	5mm thickn	ess(K)	_	ı		0.11	
Part number 1	Part number 2	Rated voltage		erature	Capacitance	Capacitance tolerance	Q (at 1MHz)	HTLT	Thickness*3 [mm]	Soldering R:Reflow	
T di c Hambor T	T di c Hamboi E	[V]	charac	teristics	[F]	Supusitanios tororanios	min	Rated voltage x %	THICKIESS [HIII]	W:Wave	
TMK021 CG0R2∏K-W			CG	C0G	0.2 p	±0.1pF, ±0.25pF	404	200	0.125±0.013	R	
TMK021 CG0R3∏K-W]	CG	C0G	0.3 p	$\pm 0.1 pF$, $\pm 0.25 pF$	406	200	0.125±0.013	R	
TMK021 CG0R4[K-W			CG	COG	0.4 p	±0.1pF, ±0.25pF	408	200	0.125±0.013	R	
TMK021 CG0R5 K-W TMK021 CG0R6 K-W		- - -	1	CG	COG	0.5 p	±0.1pF, ±0.25pF	410 412	200 200	0.125±0.013	R R
TMK021 CG0R0[K-W			CG	C0G C0G	0.6 p 0.7 p	±0.1pF, ±0.25pF ±0.1pF, ±0.25pF	414	200	0.125±0.013 0.125±0.013	R R	
TMK021 CGR75 K-W				CG	COG	0.75 p	±0.1pF, ±0.25pF	415	200	0.125±0.013	R
TMK021 CG0R8□K-W		1	CG	COG	0.8 p	±0.1pF, ±0.25pF	416	200	0.125±0.013	R	
TMK021 CG0R9∏K-W			CG	C0G	0.9 p	±0.1pF, ±0.25pF	418	200	0.125±0.013	R	
TMK021 CG010[K-W]	CG	C0G	1 p	±0.1pF, ±0.25pF	420	200	0.125±0.013	R	
TMK021 CG1R1□K-W			CG	C0G	1.1 p	$\pm 0.1 pF$, $\pm 0.25 pF$	422	200	0.125±0.013	R	
TMK021 CG1R2 K-W			CG	C0G	1.2 p	±0.1pF, ±0.25pF	424	200	0.125±0.013	R	
TMK021 CG1R3[K-W			CG	COG	1.3 p	±0.1pF, ±0.25pF	426	200	0.125±0.013	R	
TMK021 CG1R4[K-W			CG	COG	1.4 p	±0.1pF, ±0.25pF	428	200	0.125±0.013	R	
TMK021 CG1R5 K-W TMK021 CG1R6 K-W		1	CG	C0G C0G	1.5 p 1.6 p	±0.1pF, ±0.25pF ±0.1pF, ±0.25pF	430 432	200 200	0.125±0.013 0.125±0.013	R R	
TMK021 CG1R0 K-W			CG	COG	1.0 p	±0.1pF, ±0.25pF	434	200	0.125±0.013	R	
TMK021 CG1R8 K-W		1	CG	COG	1.8 p	±0.1pF, ±0.25pF	436	200	0.125±0.013	R	
TMK021 CG1R9∏K-W		1	CG	COG	1.9 p	±0.1pF, ±0.25pF	438	200	0.125±0.013	R	
TMK021 CG020[K-W		1	CG	C0G	2 p	±0.1pF, ±0.25pF	440	200	0.125±0.013	R	
TMK021 CG2R1□K-W]	CG	C0G	2.1 p	±0.1pF, ±0.25pF	442	200	0.125±0.013	R	
TMK021 CG2R2∏K-W]	CG	C0G	2.2 p	$\pm 0.1 pF$, $\pm 0.25 pF$	444	200	0.125±0.013	R	
TMK021 CG2R3 K-W			CG	C0G	2.3 p	±0.1pF, ±0.25pF	446	200	0.125±0.013	R	
TMK021 CG2R4[K-W		ļ ļ	CG	COG	2.4 p	±0.1pF, ±0.25pF	448	200	0.125±0.013	R	
TMK021 CG2R5 K-W		{	CG	COG	2.5 p	±0.1pF, ±0.25pF	450	200	0.125±0.013	R	
TMK021 CG2R6 K-W TMK021 CG2R7 K-W		{	CG	C0G C0G	2.6 p 2.7 p	±0.1pF, ±0.25pF	452 454	200 200	0.125±0.013 0.125±0.013	R R	
TMK021 CG2R7[]K-W		 	CG	COG	2.7 p 2.8 p	±0.1pF, ±0.25pF ±0.1pF, ±0.25pF	454	200	0.125±0.013 0.125±0.013	R	
TMK021 CG2R9∏K-W		† •	CG	COG	2.0 p	±0.1pF, ±0.25pF	458	200	0.125±0.013	R	
TMK021 CG030[K-W			CG	COG	3 p	±0.1pF, ±0.25pF	460	200	0.125±0.013	R	
TMK021 CG3R1[K-W		1	CG	COG	3.1 p	±0.1pF, ±0.25pF	462	200	0.125±0.013	R	
TMK021 CG3R2□K-W			CG	C0G	3.2 p	±0.1pF, ±0.25pF	464	200	0.125±0.013	R	
TMK021 CG3R3∏K-W] [CG	C0G	3.3 p	±0.1pF, ±0.25pF	466	200	0.125±0.013	R	
TMK021 CG3R4∏K-W]	CG	C0G	3.4 p	$\pm 0.1 pF$, $\pm 0.25 pF$	468	200	0.125±0.013	R	
TMK021 CG3R5∏K-W			CG	C0G	3.5 p	±0.1pF, ±0.25pF	470	200	0.125±0.013	R	
TMK021 CG3R6 K-W			CG	C0G	3.6 p	±0.1pF, ±0.25pF	472	200	0.125±0.013	R	
TMK021 CG3R7[K-W			CG	COG	3.7 p	±0.1pF, ±0.25pF	474	200	0.125±0.013	R	
TMK021 CG3R8□K-W TMK021 CG3R9□K-W		-	CG	C0G C0G	3.8 p 3.9 p	±0.1pF, ±0.25pF	476 478	200 200	0.125±0.013	R R	
TMK021 CG040 K-W		•	CG	COG	3.9 p	±0.1pF, ±0.25pF ±0.1pF, ±0.25pF	480	200	0.125±0.013 0.125±0.013	R	
TMK021 CG4R1 K-W		1	CG	COG	4.1 p	±0.1pF, ±0.25pF	482	200	0.125±0.013	R	
TMK021 CG4R2□K-W		1	CG	COG	4.2 p	±0.1pF, ±0.25pF	484	200	0.125±0.013	R	
TMK021 CG4R3∏K-W		25	CG	C0G	4.3 p	±0.1pF, ±0.25pF	486	200	0.125±0.013	R	
TMK021 CG4R4□K-W] [CG	C0G	4.4 p	±0.1pF, ±0.25pF	488	200	0.125±0.013	R	
TMK021 CG4R5∏K-W]	CG	C0G	4.5 p	$\pm 0.1 pF$, $\pm 0.25 pF$	490	200	0.125±0.013	R	
TMK021 CG4R6□K-W			CG	C0G	4.6 p	$\pm 0.1 pF, \pm 0.25 pF$	492	200	0.125±0.013	R	
TMK021 CG4R7[K-W			CG	COG	4.7 p	±0.1pF, ±0.25pF	494	200	0.125±0.013	R	
TMK021 CG4R8 K-W TMK021 CG4R9 K-W		-	CG	C0G C0G	4.8 p 4.9 p	±0.1pF, ±0.25pF ±0.1pF, ±0.25pF	496 498	200 200	0.125±0.013 0.125±0.013	R R	
TMK021 CG050 K-W		•	CG	COG	4.9 p	±0.1pF, ±0.25pF	500	200	0.125±0.013	R	
TMK021 CG5R1 K-W		1	CG	COG	5.1 p	±0.25pF, ±0.5pF	502	200	0.125±0.013	R	
TMK021 CG5R2[K-W			CG	COG	5.2 p	±0.25pF, ±0.5pF	504	200	0.125±0.013	R	
TMK021 CG5R3□K-W		1	CG	C0G	5.3 p	±0.25pF, ±0.5pF	506	200	0.125±0.013	R	
TMK021 CG5R4□K-W]	CG	C0G	5.4 p	$\pm 0.25 pF, \pm 0.5 pF$	508	200	0.125±0.013	R	
TMK021 CG5R5∏K-W]	CG	C0G	5.5 p	$\pm 0.25 pF, \pm 0.5 pF$	510	200	0.125±0.013	R	
TMK021 CG5R6□K-W			CG	C0G	5.6 p	$\pm 0.25 pF, \pm 0.5 pF$	512	200	0.125±0.013	R	
TMK021 CG5R7[K-W			CG	COG	5.7 p	±0.25pF, ±0.5pF	514	200	0.125±0.013	R	
TMK021 CG5R8[K-W		{	CG	COG	5.8 p	±0.25pF, ±0.5pF	516 518	200	0.125±0.013	R R	
TMK021 CG5R9[K-W		 	CG	C0G C0G	5.9 p 6 p	±0.25pF, ±0.5pF ±0.25pF, ±0.5pF	518	200 200	0.125±0.013 0.125±0.013	R	
TMK021 CG6R1 K-W		1 1	CG	COG	6.1 p	±0.25pF, ±0.5pF	522	200	0.125±0.013	R	
TMK021 CG6R2[K-W		1	CG	COG	6.2 p	±0.25pF, ±0.5pF	524	200	0.125±0.013	R	
TMK021 CG6R3[K-W]	CG	COG	6.3 p	±0.25pF, ±0.5pF	526	200	0.125±0.013	R	
TMK021 CG6R4[K-W] [CG	C0G	6.4 p	±0.25pF, ±0.5pF	528	200	0.125±0.013	R	
TMK021 CG6R5[K-W] [CG	C0G	6.5 p	±0.25pF, ±0.5pF	530	200	0.125±0.013	R	
TMK021 CG6R6[K-W		Į Į	CG	C0G	6.6 p	$\pm 0.25 pF$, $\pm 0.5 pF$	532	200	0.125±0.013	R	
TMK021 CG6R7[K-W			CG	COG	6.7 p	±0.25pF, ±0.5pF	534	200	0.125±0.013	R	
TMK021 CG6R8 K-W			CG	COG	6.8 p	±0.25pF, ±0.5pF	536	200	0.125±0.013	R	
TMK021 CG6R9[K-W		{	CG	COG	6.9 p	±0.25pF, ±0.5pF	538	200	0.125±0.013	R	
TMK021 CG070[K-W TMK021 CG7R1[K-W		 	CG	C0G C0G	7 p 7.1 p	±0.25pF, ±0.5pF ±0.25pF, ±0.5pF	540 542	200 200	0.125±0.013 0.125±0.013	R R	
TMK021 CG7R1 K-W		 	CG	COG	7.1 p 7.2 p	±0.25pF, ±0.5pF	544	200	0.125±0.013	R	
TMK021 CG7R3[K-W		1 1	CG	COG	7.2 p	±0.25pF, ±0.5pF	546	200	0.125±0.013	R	
TMK021 CG7R4[K-W		1	CG	COG	7.4 p	±0.25pF, ±0.5pF	548	200	0.125±0.013	R	
TMK021 CG7R5[K-W]	CG	COG	7.5 p	±0.25pF, ±0.5pF	550	200	0.125±0.013	R	
TMK021 CG7R6[K-W]	CG	COG	7.6 p	±0.25pF, ±0.5pF	552	200	0.125±0.013	R	
TMK021 CG7R7[K-W]	CG	C0G	7.7 p	±0.25pF, ±0.5pF	554	200	0.125±0.013	R	
TMK021 CG7R8[K-W] [CG	C0G	7.8 p	$\pm 0.25 pF, \pm 0.5 pF$	556	200	0.125±0.013	R	
TMK021 CG7R9[K-W		ļ [CG	C0G	7.9 p	$\pm 0.25 pF$, $\pm 0.5 pF$	558	200	0.125±0.013	R	
TMK021 CG080 K-W		j [CG	C0G	8 p	±0.25pF, ±0.5pF	560	200	0.125±0.013	R	
TMK021 CG8R1[K-W		Į	CG	COG	8.1 p	±0.25pF, ±0.5pF	562	200	0.125±0.013	R	
TMK021 CG8R2 K-W		{	CG	COG	8.2 p	±0.25pF, ±0.5pF	564	200	0.125±0.013	R	
TMK021 CG8R3 K-W TMK021 CG8R4 K-W		{	CG	COG	8.3 p	±0.25pF, ±0.5pF	566	200	0.125±0.013	R	
TMK021 CG8R4UK-W TMK021 CG8R5UK-W		 	CG CG	C0G C0G	8.4 p 8.5 p	±0.25pF, ±0.5pF ±0.25pF, ±0.5pF	568 570	200 200	0.125±0.013 0.125±0.013	R R	
VET OGGINGTIV W	1		ou	. 500	υ.υ μ	= υ.ευρι , = υ.υρι	. 0/0	200	U.120 - U.UIU		

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our product specification sheets. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/).

Part number 1	Part number 2	Rated voltage [V]		erature teristics	Capacitance [F]	Capacitance tolerance	Q (at 1MHz)	HTLT	Thickness*3 [mm]	Soldering R:Reflow
		[4]						Rated voltage x %		W:Wave
TMK021 CG8R6∏K-W			CG	C0G	8.6 p	$\pm 0.25 pF, \pm 0.5 pF$	572	200	0.125 ± 0.013	R
TMK021 CG8R7∏K-W			CG	C0G	8.7 p	$\pm 0.25 pF, \pm 0.5 pF$	574	200	0.125 ± 0.013	R
TMK021 CG8R8∏K-W			CG	C0G	8.8 p	$\pm 0.25 pF, \pm 0.5 pF$	576	200	0.125 ± 0.013	R
TMK021 CG8R9∏K-W			CG	C0G	8.9 p	$\pm 0.25 pF, \pm 0.5 pF$	578	200	0.125 ± 0.013	R
TMK021 CG090∏K-W			CG	C0G	9 p	$\pm 0.25 pF, \pm 0.5 pF$	580	200	0.125 ± 0.013	R
TMK021 CG9R1□K-W			CG	COG	9.1 p	±0.25pF, ±0.5pF	582	200	0.125 ± 0.013	R
TMK021 CG9R2∏K-W			CG	COG	9.2 p	$\pm 0.25 pF, \pm 0.5 pF$	584	200	0.125 ± 0.013	R
TMK021 CG9R3∏K-W			CG	COG	9.3 p	±0.25pF, ±0.5pF	586	200	0.125±0.013	R
TMK021 CG9R4∏K-W		25	CG	COG	9.4 p	±0.25pF, ±0.5pF	588	200	0.125±0.013	R
TMK021 CG9R5∏K-W			CG	COG	9.5 p	±0.25pF, ±0.5pF	590	200	0.125±0.013	R
TMK021 CG9R6∏K-W			CG	COG	9.6 p	±0.25pF, ±0.5pF	592	200	0.125±0.013	R
TMK021 CG9R7∏K-W			CG	COG	9.7 p	±0.25pF, ±0.5pF	594	200	0.125±0.013	R
TMK021 CG9R8∏K-W			CG	COG	9.8 p	±0.25pF, ±0.5pF	596	200	0.125±0.013	R
TMK021 CG9R9∏K-W			CG	COG	9.9 p	±0.25pF, ±0.5pF	598	200	0.125±0.013	R
TMK021 CG100DK-W			CG	COG	10 p	±0.5pF	600	200	0.125±0.013	R
TMK021 CG120JK-W			CG	COG	12 p	±5%	640	200	0.125±0.013	R
TMK021 CG150JK-W			CG	COG	15 p	±5%	700	200	0.125±0.013	R
TMK021 CG180JK-W			CG	COG	18 p	±5%	760	200	0.125±0.013	R
TMK021 CG220JK-W			CG	COG	22 p	±5%	840	200	0.125±0.013	R
TMK021 CG270JK-W			CG	COG	27 p	±5%	940	200	0.125±0.013	R
EMK021 CG330JK-W			CG	COG	33 p	±5%	1000	150	0.125±0.013	R
EMK021 CG390JK-W		16	CG	C0G	39 p	±5%	1000	150	0.125±0.013	R
EMK021 CG470JK-W		16	CG	C0G	47 p	±5%	1000	150	0.125±0.013	R
EMK021 CG560JK-W			CG	C0G	56 p	±5%	1000	150	0.125±0.013	R
LMK021 CG680JK-W			CG	C0G	68 p	±5%	1000	200	0.125±0.013	R
LMK021 CG820JK-W		10	CG	COG	82 p	±5%	1000	200	0.125±0.013	R
LMK021 CG101JK-W			CG	C0G	100 p	±5%	1000	200	0.125±0.013	R

●042TYPE

Part number 1	Part number 2	Rated voltage [V]	Tempe	erature eristics	Capacitance [F]	Capacitance tolerance	Q (at 1MHz)	HTLT	Thickness*3 [mm]	Soldering R:Reflow
		[4]	Criaract	eristics	נרו		min	Rated voltage x %		W:Wave
ΓMK042 CG0R4∏D-W			CG	C0G	0.4 p	$\pm 0.05 pF$, $\pm 0.1 pF$, $\pm 0.25 pF$	408	200	0.2 ± 0.02	R
ΓMK042 CG0R5∏D−W			CG	C0G	0.5 p	$\pm 0.05 pF$, $\pm 0.1 pF$, $\pm 0.25 pF$	410	200	0.2 ± 0.02	R
ΓMK042 CG0R6∏D-W			CG	COG	0.6 p	$\pm 0.05 pF$, $\pm 0.1 pF$, $\pm 0.25 pF$	412	200	0.2 ± 0.02	R
TMK042 CG0R7∏D-W			CG	C0G	0.7 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	414	200	0.2 ± 0.02	R
TMK042 CGR75∏D-W			CG	COG	0.75 p	±0.05pF, ±0.1pF, ±0.25pF	415	200	0.2 ± 0.02	R
TMK042 CG0R8∏D-W			CG	COG	0.8 p	±0.05pF, ±0.1pF, ±0.25pF	416	200	0.2±0.02	R
ΓMK042 CG0R9∏D-W			CG	COG	0.9 p	±0.05pF, ±0.1pF, ±0.25pF	418	200	0.2±0.02	R
ΓMK042 CG010∏D-W			CG	COG	1 p	±0.05pF, ±0.1pF, ±0.25pF	420	200	0.2 ± 0.02	R
ΓMK042 CG1R1∏D-W			CG	COG	1.1 p	±0.05pF, ±0.1pF, ±0.25pF	422	200	0.2±0.02	R
ΓMK042 CG1R2∏D-W			CG	COG	1.2 p	±0.05pF, ±0.1pF, ±0.25pF	424	200	0.2±0.02	R
ΓMK042 CG1R3∏D-W			CG	COG	1.3 p	±0.05pF, ±0.1pF, ±0.25pF	426	200	0.2±0.02	R
TMK042 CG1R4□D-W			CG	COG	1.4 p	±0.05pF, ±0.1pF, ±0.25pF	428	200	0.2±0.02	R
ΓMK042 CG1R5∏D-W			CG	COG	1.5 p	±0.05pF, ±0.1pF, ±0.25pF	430	200	0.2±0.02	R
TMK042 CG1R6∏D-W			CG	COG	1.6 p	±0.05pF, ±0.1pF, ±0.25pF	432	200	0.2±0.02	R
TMK042 CG1R0[]D W		- 	CG	COG	1.0 p	±0.05pF, ±0.1pF, ±0.25pF	434	200	0.2±0.02	R
TMK042 CG1R7□D=W		┥ !	CG	COG	1.7 p	±0.05pF, ±0.1pF, ±0.25pF ±0.05pF, ±0.1pF, ±0.25pF	434	200	0.2±0.02	R
TMK042 CG1R8UD-W TMK042 CG1R9UD-W		┥ !	CG	COG			438	200	0.2±0.02 0.2±0.02	
		_			1.9 p	±0.05pF, ±0.1pF, ±0.25pF				R
TMK042 CG020 D-W		-	CG	COG	2 p	±0.05pF, ±0.1pF, ±0.25pF	440	200	0.2±0.02	R
TMK042 CG2R1[]D-W			CG	C0G	2.1 p	±0.05pF, ±0.1pF, ±0.25pF	442	200	0.2±0.02	R
TMK042 CG2R2[]D-W			CG	C0G	2.2 p	±0.05pF, ±0.1pF, ±0.25pF	444	200	0.2±0.02	R
TMK042 CG2R3[]D-W			CG	COG	2.3 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	446	200	0.2±0.02	R
TMK042 CG2R4∏D-W			CG	C0G	2.4 p	$\pm 0.05 pF$, $\pm 0.1 pF$, $\pm 0.25 pF$	448	200	0.2 ± 0.02	R
ΓMK042 CG2R5∏D−W			CG	C0G	2.5 p	$\pm 0.05 pF$, $\pm 0.1 pF$, $\pm 0.25 pF$	450	200	0.2 ± 0.02	R
TMK042 CG2R6∏D-W			CG	C0G	2.6 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	452	200	0.2±0.02	R
TMK042 CG2R7∏D-W			CG	C0G	2.7 p	$\pm 0.05 pF$, $\pm 0.1 pF$, $\pm 0.25 pF$	454	200	0.2 ± 0.02	R
TMK042 CG2R8∏D-W			CG	COG	2.8 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	456	200	0.2 ± 0.02	R
TMK042 CG2R9∏D-W			CG	COG	2.9 p	$\pm 0.05 pF$, $\pm 0.1 pF$, $\pm 0.25 pF$	458	200	0.2 ± 0.02	R
TMK042 CG030∏D-W		25	CG	COG	3 p	±0.05pF, ±0.1pF, ±0.25pF	460	200	0.2 ± 0.02	R
TMK042 CG3R1∏D-W			CG	COG	3.1 p	±0.1pF, ±0.25pF	462	200	0.2 ± 0.02	R
TMK042 CG3R2∏D-W			CG	COG	3.2 p	±0.1pF, ±0.25pF	464	200	0.2±0.02	R
TMK042 CG3R3∏D-W			CG	COG	3.3 p	±0.1pF, ±0.25pF	466	200	0.2±0.02	R
TMK042 CG3R4∏D-W			CG	COG	3.4 p	±0.1pF, ±0.25pF	468	200	0.2±0.02	R
TMK042 CG3R5∏D-W			CG	COG	3.5 p	±0.1pF, ±0.25pF	470	200	0.2±0.02	R
TMK042 CG3R6□D-W			CG	COG	3.6 p	±0.1pF, ±0.25pF	472	200	0.2±0.02	R
TMK042 CG3R7□D-W			CG	COG	3.7 p	±0.1pF, ±0.25pF	474	200	0.2±0.02	R
TMK042 CG3R8[D-W			CG	COG	3.8 p	±0.1pF, ±0.25pF	476	200	0.2±0.02	R
TMK042 CG3R9[D-W		_	CG	COG	3.9 p	±0.1pF, ±0.25pF	478	200	0.2±0.02	R
TMK042 CG040∏D-W		-	CG	COG	4 p	±0.1pF, ±0.25pF	480	200	0.2±0.02	R
TMK042 CG040 D W		-	CG	COG	4.1 p	±0.1pF, ±0.25pF	482	200	0.2±0.02	R
TMK042 CG4R1 D-W		┥ !	CG	COG	4.1 p	±0.1pF, ±0.25pF ±0.1pF, ±0.25pF	484	200	0.2±0.02 0.2±0.02	R
		-								
TMK042 CG4R3[]D-W		-	CG	C0G	4.3 p	±0.1pF, ±0.25pF	486	200	0.2±0.02	R
TMK042 CG4R4[]D-W		-	CG	C0G	4.4 p	±0.1pF, ±0.25pF	488	200	0.2±0.02	R
TMK042 CG4R5[]D-W		⊣	CG	C0G	4.5 p	±0.1pF, ±0.25pF	490	200	0.2±0.02	R
TMK042 CG4R6∏D-W		4	CG	C0G	4.6 p	±0.1pF, ±0.25pF	492	200	0.2±0.02	R
ΓMK042 CG4R7∏D-W		_	CG	C0G	4.7 p	±0.1pF, ±0.25pF	494	200	0.2±0.02	R
ΓMK042 CG4R8∏D-W		⊿	CG	C0G	4.8 p	±0.1pF, ±0.25pF	496	200	0.2±0.02	R
rmk042 cg4R9∏D-w		」	CG	C0G	4.9 p	±0.1pF, ±0.25pF	498	200	0.2±0.02	R
ΓMK042 CG050∏D-W		_	CG	C0G	5 p	$\pm 0.1 pF$, $\pm 0.25 pF$	500	200	0.2±0.02	R
ΓMK042 CG5R1∏D-W			CG	C0G	5.1 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	502	200	0.2 ± 0.02	R
ΓMK042 CG5R2∏D-W			CG	COG	5.2 p	±0.1pF, ±0.25pF, ±0.5pF	504	200	0.2±0.02	R
ΓMK042 CG5R3∏D-W			CG	COG	5.3 p	±0.1pF, ±0.25pF, ±0.5pF	506	200	0.2±0.02	R
ΓMK042 CG5R4∏D−W			CG	COG	5.4 p	±0.1pF, ±0.25pF, ±0.5pF	508	200	0.2±0.02	R
ΓMK042 CG5R5∏D-W		7	CG	COG	5.5 p	±0.1pF, ±0.25pF, ±0.5pF	510	200	0.2±0.02	R
TMK042 CG5R6∏D-W		┪ !	CG	COG	5.6 p	±0.1pF, ±0.25pF, ±0.5pF	512	200	0.2±0.02	R
TMK042 CG5R7∏D-W		╡	CG	COG	5.7 p	±0.1pF, ±0.25pF, ±0.5pF	514	200	0.2±0.02	R

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our product specification sheets. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/).

							0			Caldania
Part number 1	Part number 2	Rated voltage	Temperature characteristics		Capacitance	Capacitance tolerance	Q (at 1MHz)	HTLT	Thickness*3 [mm]	Soldering R:Reflow
		[V]			[F]		min	Rated voltage x %		W:Wave
TMK042 CG5R8 D-W		4	CG	COG	5.8 p	±0.1pF, ±0.25pF, ±0.5pF	516	200	0.2±0.02	R
TMK042 CG5R9∏D-W TMK042 CG060∏D-W		-	CG	C0G C0G	5.9 p	±0.1pF, ±0.25pF, ±0.5pF	518 520	200 200	0.2±0.02	R R
TMK042 CG060∐D-W		-	CG	COG	6 p 6.1 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	520	200	0.2±0.02 0.2±0.02	R
TMK042 CG6R2∏D-W			CG	COG	6.2 p	±0.1pF, ±0.25pF, ±0.5pF	524	200	0.2±0.02	R
TMK042 CG6R3□D-W			CG	COG	6.3 p	±0.1pF, ±0.25pF, ±0.5pF	526	200	0.2±0.02	R
TMK042 CG6R4∏D-W			CG	C0G	6.4 p	±0.1pF, ±0.25pF, ±0.5pF	528	200	0.2±0.02	R
TMK042 CG6R5∏D-W			CG	C0G	6.5 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	530	200	0.2±0.02	R
TMK042 CG6R6 D-W			CG	COG	6.6 p	±0.1pF, ±0.25pF, ±0.5pF	532	200	0.2±0.02	R
TMK042 CG6R7□D-W		_	CG	COG	6.7 p	±0.1pF, ±0.25pF, ±0.5pF	534	200	0.2±0.02	R
TMK042 CG6R8[]D-W TMK042 CG6R9[]D-W			CG	C0G C0G	6.8 p 6.9 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	536 538	200 200	0.2±0.02 0.2±0.02	R R
TMK042 CG0R9DD-W		-	CG	COG	7 p	±0.1pF, ±0.25pF, ±0.5pF	540	200	0.2±0.02	R
TMK042 CG7R1 D-W			CG	COG	7.1 p	±0.1pF, ±0.25pF, ±0.5pF	542	200	0.2±0.02	R
TMK042 CG7R2□D-W			CG	COG	7.2 p	±0.1pF, ±0.25pF, ±0.5pF	544	200	0.2±0.02	R
TMK042 CG7R3[]D-W			CG	C0G	7.3 p	±0.1pF, ±0.25pF, ±0.5pF	546	200	0.2±0.02	R
TMK042 CG7R4∏D-W			CG	C0G	7.4 p	±0.1pF, ±0.25pF, ±0.5pF	548	200	0.2±0.02	R
TMK042 CG7R5□D-W			CG	C0G	7.5 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	550	200	0.2 ± 0.02	R
TMK042 CG7R6 D-W		-	CG	COG	7.6 p	±0.1pF, ±0.25pF, ±0.5pF	552	200	0.2±0.02	R
TMK042 CG7R7 D-W		-	CG	COG	7.7 p	±0.1pF, ±0.25pF, ±0.5pF	554	200 200	0.2±0.02	R
TMK042 CG7R8[]D-W TMK042 CG7R9[]D-W		┥ !	CG	C0G C0G	7.8 p 7.9 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	556 558	200	0.2±0.02 0.2±0.02	R R
TMK042 CG7R9□D=W		┪	CG	COG	7.9 p	±0.1pF, ±0.25pF, ±0.5pF	560	200	0.2±0.02 0.2±0.02	R
TMK042 CG8R1□D-W		1	CG	COG	8.1 p	±0.1pF, ±0.25pF, ±0.5pF	562	200	0.2±0.02	R
TMK042 CG8R2[D-W			CG	COG	8.2 p	±0.1pF, ±0.25pF, ±0.5pF	564	200	0.2±0.02	R
TMK042 CG8R3[D-W			CG	C0G	8.3 p	±0.1pF, ±0.25pF, ±0.5pF	566	200	0.2±0.02	R
TMK042 CG8R4∏D-W			CG	COG	8.4 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	568	200	0.2 ± 0.02	R
TMK042 CG8R5∏D-W			CG	C0G	8.5 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	570	200	0.2 ± 0.02	R
TMK042 CG8R6□D-W			CG	C0G	8.6 p	±0.1pF, ±0.25pF, ±0.5pF	572	200	0.2±0.02	R
TMK042 CG8R7 D-W		_	CG	COG	8.7 p	±0.1pF, ±0.25pF, ±0.5pF	574	200	0.2±0.02	R
TMK042 CG8R8[]D-W TMK042 CG8R9[]D-W		_	CG	C0G C0G	8.8 p 8.9 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	576 578	200 200	0.2±0.02 0.2±0.02	R R
TMK042 CG080 D-W		-	CG	COG	9 p	±0.1pF, ±0.25pF, ±0.5pF	580	200	0.2±0.02	R
TMK042 CG9R1 □D-W		25	CG	COG	9.1 p	±0.1pF, ±0.25pF, ±0.5pF	582	200	0.2±0.02	R
TMK042 CG9R2□D-W			CG	COG	9.2 p	±0.1pF, ±0.25pF, ±0.5pF	584	200	0.2±0.02	R
TMK042 CG9R3[D-W			CG	C0G	9.3 p	±0.1pF, ±0.25pF, ±0.5pF	586	200	0.2±0.02	R
TMK042 CG9R4[]D-W			CG	COG	9.4 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	588	200	0.2 ± 0.02	R
TMK042 CG9R5∏D-W			CG	C0G	9.5 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	590	200	0.2 ± 0.02	R
TMK042 CG9R6□D-W			CG	C0G	9.6 p	±0.1pF, ±0.25pF, ±0.5pF	592	200	0.2±0.02	R
TMK042 CG9R7[D-W		_	CG	COG	9.7 p	±0.1pF, ±0.25pF, ±0.5pF	594	200	0.2±0.02	R
TMK042 CG9R8∏D-W TMK042 CG9R9∏D-W		-	CG	C0G C0G	9.8 p 9.9 p	±0.1pF, ±0.25pF, ±0.5pF	596 598	200 200	0.2±0.02 0.2±0.02	R R
TMK042 CG100DD-W		_	CG	COG	9.9 p	±0.1pF, ±0.25pF, ±0.5pF ±0.5pF	600	200	0.2±0.02	R
TMK042 CG110JD-W		-	CG	COG	11 p	±5%	620	200	0.2±0.02	R
TMK042 CG120JD-W			CG	COG	12 p	±5%	640	200	0.2±0.02	R
TMK042 CG130JD-W]	CG	COG	13 p	±5%	660	200	0.2±0.02	R
TMK042 CG150JD-W			CG	C0G	15 p	±5%	700	200	0.2±0.02	R
TMK042 CG160JC-W		」	CG	C0G	16 p	±5%	720	200	0.2±0.02	R
TMK042 CG180JC-W		-	CG	C0G	18 p	±5%	760	200	0.2±0.02	R
TMK042 CG200JC-W		-	CG	COG	20 p	±5%	800	200	0.2±0.02	R
TMK042 CG220JC-W		-	CG	COG	22 p	±5%	840	200	0.2±0.02	R
TMK042 CG240JC-W TMK042 CG270JC-W		1	CG	C0G C0G	24 p 27 p	±5% ±5%	940	200 200	0.2±0.02 0.2±0.02	R R
TMK042 CG2703C-W		┧	CG	COG	30 p	±5%	1000	200	0.2±0.02	R
TMK042 CG330JC-W		1	CG	COG	33 p	±5%	1000	200	0.2±0.02	R
TMK042 CG360JC-W		1	CG	COG	36 p	±5%	1000	200	0.2±0.02	R
TMK042 CG390JC-W]	CG	C0G	39 p	±5%	1000	200	0.2±0.02	R
TMK042 CG430JC-W]	CG	C0G	43 p	±5%	1000	200	0.2±0.02	R
TMK042 CG470JC-W		」	CG	C0G	47 p	±5%	1000	200	0.2±0.02	R
TMK042 CG510JC-W		」	CG	C0G	51 p	±5%	1000	200	0.2±0.02	R
TMK042 CG560JC-W		-	CG	COG	56 p	±5%	1000	200	0.2±0.02	R
TMK042 CG620JC-W		-	CG	C0G	62 p	±5%	1000	200	0.2±0.02	R
TMK042 CG680JC-W TMK042 CG750JC-W		┥ !	CG	C0G C0G	68 p 75 p	±5% ±5%	1000	200 200	0.2±0.02 0.2±0.02	R R
TMK042 CG820JC-W		1	CG	COG	75 p 82 p	±5%	1000	200	0.2±0.02 0.2±0.02	R
TMK042 CG910JC-W		┪	CG	COG	91 p	±5%	1000	200	0.2±0.02	R
		_ i	CG	COG	100 p	±5%	1000	200	0.2±0.02	R

[Temperature Characteristic CG : CG/C0G($-55 \sim +125^{\circ}$ C)] 0.2mm thickness(C,D)													
Part number 1	Part number 2	Rated voltage		erature	Capacitance	Capacitance tolerance	Q (at 1MHz)	HTLT	Thickness*3 [mm]	Soldering R:Reflow			
T di t Hambor T	T dre namber 2	[V]	charact	eristics	[F]	oupuoitanoo toloranoo	min	Rated voltage x %	Triickness [iiiii]	W:Wave			
EMK042 CG0R4[]D-W			CG	COG	0.4 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	408	200	0.2 ± 0.02	R			
EMK042 CG0R5[]D-W			CG	COG	0.5 p	±0.05pF, ±0.1pF, ±0.25pF	410	200	0.2 ± 0.02	R			
EMK042 CG0R6 D-W			CG	C0G	0.6 p	±0.05pF, ±0.1pF, ±0.25pF	412	200	0.2 ± 0.02	R			
EMK042 CG0R7[]D-W			CG	COG	0.7 p	±0.05pF, ±0.1pF, ±0.25pF	414	200	0.2 ± 0.02	R			
EMK042 CGR75[]D-W			CG	COG	0.75 p	±0.05pF, ±0.1pF, ±0.25pF	415	200	0.2 ± 0.02	R			
EMK042 CG0R8[]D-W			CG	COG	0.8 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	416	200	0.2 ± 0.02	R			
EMK042 CG0R9[]D-W			CG	COG	0.9 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	418	200	0.2 ± 0.02	R			
EMK042 CG010 D-W			CG	COG	1 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	420	200	0.2 ± 0.02	R			
EMK042 CG1R1[D-W		16	CG	COG	1.1 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	422	200	0.2 ± 0.02	R			
EMK042 CG1R2[]D-W			CG	COG	1.2 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	424	200	0.2 ± 0.02	R			
EMK042 CG1R3[D-W			CG	COG	1.3 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	426	200	0.2 ± 0.02	R			
EMK042 CG1R4[]D-W			CG	COG	1.4 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	428	200	0.2 ± 0.02	R			
EMK042 CG1R5[D-W			CG	COG	1.5 p	±0.05pF, ±0.1pF, ±0.25pF	430	200	0.2 ± 0.02	R			
EMK042 CG1R6□D-W			CG	C0G	1.6 p	±0.05pF, ±0.1pF, ±0.25pF	432	200	0.2 ± 0.02	R			
EMK042 CG1R7[]D-W			CG	C0G	1.7 p	±0.05pF, ±0.1pF, ±0.25pF	434	200	0.2±0.02	R			
EMK042 CG1R8[]D-W			CG	COG	1.8 p	±0.05pF, ±0.1pF, ±0.25pF	436	200	0.2 ± 0.02	R			
EMK042 CG1R9[]D-W			CG	COG	1.9 p	$\pm 0.05 pF$, $\pm 0.1 pF$, $\pm 0.25 pF$	438	200	0.2 ± 0.02	R			

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our product specification sheets. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/).

Part number 1	Part number 2	Rated voltage [V]		erature eristics	Capacitance [F]	Capacitance tolerance	Q (at 1MHz) min	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
EMK042 CG020 D-W			CG	C0G	2 p	±0.05pF, ±0.1pF, ±0.25pF	440	200	0.2±0.02	R
EMK042 CG2R1[]D-W			CG	C0G	2.1 p	±0.05pF, ±0.1pF, ±0.25pF	442	200	0.2 ± 0.02	R
EMK042 CG2R2[]D-W			CG	C0G	2.2 p	± 0.05 pF, ± 0.1 pF, ± 0.25 pF	444	200	0.2±0.02	R
EMK042 CG2R3[]D-W			CG	COG	2.3 p	±0.05pF, ±0.1pF, ±0.25pF	446	200	0.2±0.02	R
EMK042 CG2R4 D-W EMK042 CG2R5 D-W		1	CG	C0G C0G	2.4 p 2.5 p	±0.05pF, ±0.1pF, ±0.25pF ±0.05pF, ±0.1pF, ±0.25pF	448 450	200 200	0.2±0.02 0.2±0.02	R R
EMK042 CG2R6 D-W		-	CG	COG	2.5 p	±0.05pF, ±0.1pF, ±0.25pF	452	200	0.2±0.02	R
EMK042 CG2R7[]D-W		1	CG	COG	2.7 p	±0.05pF, ±0.1pF, ±0.25pF	454	200	0.2±0.02	R
EMK042 CG2R8[]D-W			CG	COG	2.8 p	±0.05pF, ±0.1pF, ±0.25pF	456	200	0.2±0.02	R
EMK042 CG2R9[]D-W		1	CG	COG	2.9 p	±0.05pF, ±0.1pF, ±0.25pF	458	200	0.2±0.02	R
EMK042 CG030[D-W			CG	C0G	3 p	±0.05pF, ±0.1pF, ±0.25pF	460	200	0.2 ± 0.02	R
EMK042 CG3R1[]D-W			CG	C0G	3.1 p	±0.1pF, ±0.25pF	462	200	0.2±0.02	R
EMK042 CG3R2[]D-W		-	CG	COG	3.2 p	±0.1pF, ±0.25pF	464	200	0.2±0.02	R
EMK042 CG3R3[]D-W EMK042 CG3R4[]D-W		1	CG	C0G C0G	3.3 p 3.4 p	±0.1pF, ±0.25pF ±0.1pF, ±0.25pF	466 468	200 200	0.2±0.02 0.2±0.02	R R
EMK042 CG3R4DD-W		1	CG	COG	3.4 p	±0.1pF, ±0.25pF ±0.1pF, ±0.25pF	470	200	0.2±0.02 0.2±0.02	R
EMK042 CG3R6 D-W		1	CG	COG	3.6 p	±0.1pF, ±0.25pF	472	200	0.2±0.02	R
EMK042 CG3R7[]D-W		1	CG	COG	3.7 p	±0.1pF, ±0.25pF	474	200	0.2±0.02	R
EMK042 CG3R8[]D-W			CG	C0G	3.8 p	±0.1pF, ±0.25pF	476	200	0.2±0.02	R
EMK042 CG3R9[]D-W			CG	C0G	3.9 p	±0.1pF, ±0.25pF	478	200	0.2 ± 0.02	R
EMK042 CG040 D-W			CG	C0G	4 p	±0.1pF, ±0.25pF	480	200	0.2±0.02	R
EMK042 CG4R1[]D-W			CG	COG	4.1 p	±0.1pF, ±0.25pF	482	200	0.2±0.02	R
EMK042 CG4R2 D-W EMK042 CG4R3 D-W		1	CG	C0G C0G	4.2 p 4.3 p	±0.1pF, ±0.25pF ±0.1pF, ±0.25pF	484 486	200 200	0.2±0.02 0.2±0.02	R R
EMK042 CG4R4[D-W		 	CG	COG	4.3 p 4.4 p	±0.1pF, ±0.25pF	488	200	0.2±0.02 0.2±0.02	R
EMK042 CG4R5 D-W			CG	COG	4.5 p	±0.1pF, ±0.25pF	490	200	0.2±0.02	R
EMK042 CG4R6 D-W]	CG	COG	4.6 p	±0.1pF, ±0.25pF	492	200	0.2±0.02	R
EMK042 CG4R7[]D-W]	CG	C0G	4.7 p	±0.1pF, ±0.25pF	494	200	0.2±0.02	R
EMK042 CG4R8[]D-W			CG	C0G	4.8 p	±0.1pF, ±0.25pF	496	200	0.2±0.02	R
EMK042 CG4R9[]D-W			CG	COG	4.9 p	±0.1pF, ±0.25pF	498	200	0.2±0.02	R
EMK042 CG050[]D-W EMK042 CG5R1 []D-W			CG	C0G C0G	5 p 5.1 p	±0.1pF, ±0.25pF ±0.1pF, ±0.25pF, ±0.5pF	500 502	200 200	0.2±0.02 0.2±0.02	R R
EMK042 CG5R1 D-W		1	CG	COG	5.1 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	504	200	0.2±0.02 0.2±0.02	R
EMK042 CG5R3[]D-W		1	CG	COG	5.2 p	±0.1pF, ±0.25pF, ±0.5pF	506	200	0.2±0.02	R
EMK042 CG5R4[]D-W		1	CG	COG	5.4 p	±0.1pF, ±0.25pF, ±0.5pF	508	200	0.2±0.02	R
EMK042 CG5R5[]D-W		1	CG	COG	5.5 p	±0.1pF, ±0.25pF, ±0.5pF	510	200	0.2±0.02	R
EMK042 CG5R6 D-W			CG	COG	5.6 p	±0.1pF, ±0.25pF, ±0.5pF	512	200	0.2±0.02	R
EMK042 CG5R7[]D-W			CG	COG	5.7 p	±0.1pF, ±0.25pF, ±0.5pF	514	200	0.2±0.02	R
EMK042 CG5R8 D-W			CG	C0G	5.8 p	±0.1pF, ±0.25pF, ±0.5pF	516	200	0.2±0.02	R
EMK042 CG5R9[]D-W			CG	COG	5.9 p	±0.1pF, ±0.25pF, ±0.5pF	518	200	0.2±0.02	R
EMK042 CG060 D-W		-	CG	C0G C0G	6 p	±0.1pF, ±0.25pF, ±0.5pF	520	200	0.2±0.02	R R
EMK042 CG6R1□D-W EMK042 CG6R2□D-W		1	CG	COG	6.1 p 6.2 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	522 524	200 200	0.2±0.02 0.2±0.02	R
EMK042 CG6R3 D-W		1	CG	COG	6.3 p	±0.1pF, ±0.25pF, ±0.5pF	526	200	0.2±0.02	R
EMK042 CG6R4[]D-W		1	CG	COG	6.4 p	±0.1pF, ±0.25pF, ±0.5pF	528	200	0.2±0.02	R
EMK042 CG6R5[]D-W		16	CG	C0G	6.5 p	±0.1pF, ±0.25pF, ±0.5pF	530	200	0.2±0.02	R
EMK042 CG6R6[]D-W			CG	COG	6.6 p	±0.1pF, ±0.25pF, ±0.5pF	532	200	0.2±0.02	R
EMK042 CG6R7 D-W			CG	C0G	6.7 p	±0.1pF, ±0.25pF, ±0.5pF	534	200	0.2±0.02	R
EMK042 CG6R8[]D-W			CG	COG	6.8 p	±0.1pF, ±0.25pF, ±0.5pF	536	200	0.2±0.02	R
EMK042 CG6R9 D-W EMK042 CG070 D-W		-	CG	C0G C0G	6.9 p 7 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	538 540	200 200	0.2±0.02 0.2±0.02	R R
EMK042 CG070 D-W		-	CG	COG	7,1 p	±0.1pF, ±0.25pF, ±0.5pF	542	200	0.2±0.02	R
EMK042 CG7R2 D-W		1	CG	COG	7.1 p	±0.1pF, ±0.25pF, ±0.5pF	544	200	0.2±0.02	R
EMK042 CG7R3 D-W		1	CG	COG	7.3 p	±0.1pF, ±0.25pF, ±0.5pF	546	200	0.2±0.02	R
EMK042 CG7R4[]D-W			CG	COG	7.4 p	±0.1pF, ±0.25pF, ±0.5pF	548	200	0.2±0.02	R
EMK042 CG7R5[]D-W			CG	C0G	7.5 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	550	200	0.2±0.02	R
EMK042 CG7R6[]D-W			CG	C0G	7.6 p	±0.1pF, ±0.25pF, ±0.5pF	552	200	0.2±0.02	R
EMK042 CG7R7[D-W		-	CG	COG	7.7 p	±0.1pF, ±0.25pF, ±0.5pF	554 EE6	200	0.2±0.02	R
EMK042 CG7R8 D-W EMK042 CG7R9 D-W		- I	CG	C0G C0G	7.8 p 7.9 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	556 558	200 200	0.2±0.02 0.2±0.02	R R
EMK042 CG080 D-W		1	CG	COG	7.5 p	±0.1pF, ±0.25pF, ±0.5pF	560	200	0.2±0.02	R
EMK042 CG8R1 D-W			CG	COG	8.1 p	±0.1pF, ±0.25pF, ±0.5pF	562	200	0.2±0.02	R
EMK042 CG8R2[D-W]	CG	C0G	8.2 p	±0.1pF, ±0.25pF, ±0.5pF	564	200	0.2±0.02	R
EMK042 CG8R3[D-W		ļ [CG	C0G	8.3 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	566	200	0.2±0.02	R
EMK042 CG8R4[]D-W			CG	COG	8.4 p	±0.1pF, ±0.25pF, ±0.5pF	568	200	0.2±0.02	R
EMK042 CG8R5 D-W			CG	C0G	8.5 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	570 572	200	0.2±0.02	R R
EMK042 CG8R6 D-W EMK042 CG8R7 D-W		 	CG	C0G C0G	8.6 p 8.7 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	572 574	200 200	0.2±0.02 0.2±0.02	R
EMK042 CG8R8 D-W			CG	COG	8.7 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	576	200	0.2±0.02 0.2±0.02	R
EMK042 CG8R9 D-W		1 1	CG	COG	8.9 p	±0.1pF, ±0.25pF, ±0.5pF	578	200	0.2±0.02	R
EMK042 CG090[]D-W		1 1	CG	COG	9 p	±0.1pF, ±0.25pF, ±0.5pF	580	200	0.2±0.02	R
EMK042 CG9R1 D-W			CG	COG	9.1 p	±0.1pF, ±0.25pF, ±0.5pF	582	200	0.2±0.02	R
EMK042 CG9R2[]D-W] [CG	C0G	9.2 p	± 0.1 pF, ± 0.25 pF, ± 0.5 pF	584	200	0.2±0.02	R
EMK042 CG9R3 D-W] [CG	COG	9.3 p	±0.1pF, ±0.25pF, ±0.5pF	586	200	0.2±0.02	R
EMK042 CG9R4[]D-W			CG	COG	9.4 p	±0.1pF, ±0.25pF, ±0.5pF	588	200	0.2±0.02	R
EMK042 CG9R5[]D-W		-{ 	CG	C0G C0G	9.5 p	±0.1pF, ±0.25pF, ±0.5pF	590	200 200	0.2±0.02	R
EMK042 CG9R6 D-W EMK042 CG9R7 D-W		 	CG	COG	9.6 p 9.7 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	592 594	200	0.2±0.02 0.2±0.02	R R
EMK042 CG9R7 D-W			CG	COG	9.7 p 9.8 p	±0.1pF, ±0.25pF, ±0.5pF ±0.1pF, ±0.25pF, ±0.5pF	594	200	0.2±0.02 0.2±0.02	R
EMK042 CG9R9 D-W		1	CG	COG	9.9 p	±0.1pF, ±0.25pF, ±0.5pF	598	200	0.2±0.02	R
EMK042 CG100DD-W		1	CG	COG	10 p	±0.5pF	600	200	0.2±0.02	R
EMK042 CG110JD-W]	CG	C0G	11 p	±5%	620	200	0.2±0.02	R
EMK042 CG120JD-W]	CG	C0G	12 p	±5%	640	200	0.2±0.02	R
EMK042 CG130JD-W] [CG	COG	13 p	±5%	660	200	0.2±0.02	R
EMK042 CG150JD-W		Į ļ	CG	COG	15 p	±5%	700	200	0.2±0.02	R
EMK042 CG160JC-W		-	CG	C0G C0G	16 p	±5% +5%	720 760	200 200	0.2±0.02 0.2±0.02	R
FMKUNG CC100 IO W	i e	i L			18 p	±5%				R
EMK042 CG180JC-W		Г	CC	COC	20 ~	+50%	RUU	200	0.2 + 0.02	D
EMK042 CG180JC-W EMK042 CG200JC-W EMK042 CG220JC-W]	CG	C0G C0G	20 p 22 p	±5% ±5%	800 840	200 200	0.2±0.02 0.2±0.02	R R

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our product specification sheets. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/).

Part number 1	Part number 2	Rated voltage [V]	Tempe charact		Capacitance [F]	Capacitance tolerance	Q (at 1MHz) min	HTLT Rated voltage x %	Thickness*3 [mm]	Soldering R:Reflow W:Wave
EMK042 CG270JC-W			CG	COG	27 p	±5%	940	200	0.2 ± 0.02	R
EMK042 CG300JC-W			CG	COG	30 p	±5%	1000	200	0.2 ± 0.02	R
EMK042 CG330JC-W			CG	COG	33 p	±5%	1000	200	0.2 ± 0.02	R
EMK042 CG360JC-W			CG	COG	36 p	±5%	1000	200	0.2 ± 0.02	R
EMK042 CG390JC-W			CG	COG	39 p	±5%	1000	200	0.2 ± 0.02	R
EMK042 CG430JC-W			CG	COG	43 p	±5%	1000	200	0.2 ± 0.02	R
EMK042 CG470JC-W			CG	COG	47 p	±5%	1000	200	0.2 ± 0.02	R
EMK042 CG510JC-W			CG	COG	51 p	±5%	1000	200	0.2 ± 0.02	R
EMK042 CG560JC-W			CG	COG	56 p	±5%	1000	200	0.2 ± 0.02	R
EMK042 CG620JC-W		16	CG	C0G	62 p	±5%	1000	200	0.2 ± 0.02	R
EMK042 CG680JC-W			CG	COG	68 p	±5%	1000	200	0.2 ± 0.02	R
EMK042 CG750JC-W			CG	COG	75 p	±5%	1000	200	0.2 ± 0.02	R
EMK042 CG820JC-W			CG	COG	82 p	±5%	1000	200	0.2 ± 0.02	R
EMK042 CG910JC-W			CG	COG	91 p	±5%	1000	200	0.2 ± 0.02	R
EMK042 CG101JC-W			CG	COG	100 p	±5%	1000	200	0.2 ± 0.02	R
EMK042 CG221JC-W			CG	COG	220 p	±5%	1000	200	0.2±0.02	R
EMK042 CG241JC-W			CG	COG	240 p	±5%	1000	200	0.2±0.02	R
EMK042 CG271JC-W			CG	COG	270 р	±5%	1000	200	0.2±0.02	R
EMK042 CG331JC-W			CG	C0G	330 р	±5%	1000	200	0.2±0.02	R

●063TYPE

[Temperature Characteristic CG : CG/C0G($-55 \sim +125 ^{\circ}$ C)] 0.3mm thickness(T)

Temperature Charac		Rated voltage		erature	Capacitance		Q	HTLT	*2	Soldering
Part number 1	Part number 2	[V]		eristics	[F]	Capacitance tolerance	(at 1MHz) min	Rated voltage x %	Thickness*3 [mm]	R:Reflow W:Wave
UMK063 CG200JT-F			CG	COG	20 p	±5%	800	200	0.3±0.03	R
UMK063 CG220JT-F			CG	COG	22 p	±5%	840	200	0.3±0.03	R
UMK063 CG240JT-F			CG	COG	24 p	±5%	880	200	0.3±0.03	R
UMK063 CG270JT-F			CG	COG	27 p	±5%	940	200	0.3±0.03	R
UMK063 CG300JT-F			CG	COG	30 p	±5%	1000	200	0.3±0.03	R
UMK063 CG330JT-F			CG	COG	33 p	±5%	1000	200	0.3 ± 0.03	R
UMK063 CG360JT-F			CG	COG	36 p	±5%	1000	200	0.3±0.03	R
UMK063 CG390JT-F			CG	COG	39 p	±5%	1000	200	0.3±0.03	R
UMK063 CG430JT-F			CG	COG	43 p	±5%	1000	200	0.3±0.03	R
UMK063 CG470JT-F			CG	COG	47 p	±5%	1000	200	0.3±0.03	R
UMK063 CG510JT-F			CG	COG	51 p	±5%	1000	200	0.3±0.03	R
UMK063 CG560JT-F		1	CG	COG	56 p	±5%	1000	200	0.3±0.03	R
UMK063 CG620JT-F		50	CG	COG	62 p	±5%	1000	200	0.3±0.03	R
UMK063 CG680JT-F			CG	COG	68 p	±5%	1000	200	0.3±0.03	R
UMK063 CG750JT-F			CG	COG	75 p	±5%	1000	200	0.3±0.03	R
UMK063 CG820JT-F			CG	COG	82 p	±5%	1000	200	0.3±0.03	R
UMK063 CG910JT-F			CG	COG	91 p	±5%	1000	200	0.3 ± 0.03	R
UMK063 CG101JT-F			CG	COG	100 p	±5%	1000	200	0.3±0.03	R
UMK063 CG111JT-F			CG	COG	110 p	±5%	1000	200	0.3±0.03	R
UMK063 CG121JT-F			CG	COG	120 p	±5%	1000	200	0.3 ± 0.03	R
UMK063 CG131JT-F			CG	COG	130 p	±5%	1000	200	0.3 ± 0.03	R
UMK063 CG151JT-F			CG	COG	150 p	±5%	1000	200	0.3 ± 0.03	R
UMK063 CG181JT-F			CG	COG	180 p	±5%	1000	200	0.3 ± 0.03	R
UMK063 CG201JT-F			CG	COG	200 p	±5%	1000	200	0.3 ± 0.03	R
UMK063 CG221JT-F			CG	COG	220 p	±5%	1000	200	0.3 ± 0.03	R
TMK063 CG241JT-F			CG	COG	240 p	±5%	1000	200	0.3 ± 0.03	R
TMK063 CG271JT-F			CG	COG	270 p	±5%	1000	200	0.3 ± 0.03	R
TMK063 CG301JT-F			CG	COG	300 p	±5%	1000	200	0.3 ± 0.03	R
TMK063 CG331JT-F] [CG	COG	330 p	±5%	1000	200	0.3 ± 0.03	R
TMK063 CG361JT-F			CG	COG	360 p	±5%	1000	200	0.3 ± 0.03	R
TMK063 CG391JT-F			CG	COG	390 р	±5%	1000	200	0.3 ± 0.03	R
TMK063 CG431JT-F			CG	COG	430 p	±5%	1000	200	0.3 ± 0.03	R
TMK063 CG471JT-F		25	CG	C0G	470 p	±5%	1000	200	0.3 ± 0.03	R
TMK063 CG511JT-F			CG	COG	510 p	±5%	1000	200	0.3 ± 0.03	R
TMK063 CG561JT-F			CG	COG	560 p	±5%	1000	200	0.3 ± 0.03	R
TMK063 CG621JT-F			CG	COG	620 p	±5%	1000	200	0.3 ± 0.03	R
TMK063 CG681JT-F			CG	COG	680 p	±5%	1000	200	0.3 ± 0.03	R
TMK063 CG751JT-F			CG	COG	750 p	±5%	1000	200	0.3 ± 0.03	R
TMK063 CG821JT-F] [CG	COG	820 p	±5%	1000	200	0.3 ± 0.03	R
TMK063 CG911JT-F			CG	COG	910 p	±5%	1000	200	0.3 ± 0.03	R
TMK063 CG102JT-F			CG	COG	1000 p	±5%	1000	200	0.3 ± 0.03	R

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our product specification sheets. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/).

●105TYPE

【Temperature Characteristic CG : CG/C0G(−55~+125°C)】 0.5mm thickness(V)

Temperature Charac	teristic GG : GG/C	Rated voltage		erature	Capacitance	S(V)	Q	HTLT		Soldering
Part number 1	Part number 2	[V]		eristics	[F]	Capacitance tolerance	(at 1MHz) min	Rated voltage x %	Thickness*3 [mm]	R:Reflow W:Wave
UMK105 CG0R5CV-F			CG	COG	0.5 p	±0.25pF	410	200	0.5±0.05	R
UMK105 CG010CV-F			CG	COG	1 p	±0.25pF	420	200	0.5±0.05	R
UMK105 CG1R5CV-F			CG	COG	1.5 p	±0.25pF	430	200	0.5±0.05	R
UMK105 CG020CV-F			CG	COG	2 p	±0.25pF	440	200	0.5±0.05	R
UMK105 CG030CV-F			CG	COG	3 p	±0.25pF	460	200	0.5±0.05	R
UMK105 CG040CV-F			CG	COG	4 p	±0.25pF	480	200	0.5±0.05	R
UMK105 CG050CV-F			CG	COG	5 p	±0.25pF	500	200	0.5±0.05	R
UMK105 CG060DV-F			CG	COG	6 p	±0.5pF	520	200	0.5±0.05	R
UMK105 CG070DV-F			CG	COG	7 p	±0.5pF	540	200	0.5±0.05	R
UMK105 CG080DV-F			CG	COG	8 p	±0.5pF	560	200	0.5±0.05	R
UMK105 CG090DV-F			CG	COG	9 p	±0.5pF	580	200	0.5±0.05	R
UMK105 CG100DV-F			CG	COG	10 p	±0.5pF	600	200	0.5±0.05	R
UMK105 CG120JV-F			CG	COG	12 p	±5%	640	200	0.5±0.05	R
UMK105 CG150JV-F			CG	COG	15 p	±5%	700	200	0.5±0.05	R
UMK105 CG180JV-F			CG	COG	18 p	±5%	760	200	0.5±0.05	R
UMK105 CG220JV-F			CG	COG	22 p	±5%	840	200	0.5±0.05	R
UMK105 CG270JV-F			CG	COG	27 p	±5%	940	200	0.5±0.05	R
UMK105 CG330JV-F		F0	CG	COG	33 p	±5%	1000	200	0.5±0.05	R
UMK105 CG390JV-F		50	CG	COG	39 p	±5%	1000	200	0.5±0.05	R
UMK105 CG470JV-F			CG	COG	47 p	±5%	1000	200	0.5±0.05	R
UMK105 CG560JV-F			CG	COG	56 p	±5%	1000	200	0.5±0.05	R
UMK105 CG680JV-F			CG	COG	68 p	±5%	1000	200	0.5±0.05	R
UMK105 CG820JV-F			CG	COG	82 p	±5%	1000	200	0.5 ± 0.05	R
UMK105 CG101JV-F			CG	COG	100 p	±5%	1000	200	0.5 ± 0.05	R
UMK105 CG121JV-F			CG	COG	120 p	±5%	1000	200	0.5±0.05	R
UMK105 CG151JV-F			CG	COG	150 p	±5%	1000	200	0.5±0.05	R
UMK105 CG181JV-F			CG	COG	180 p	±5%	1000	200	0.5±0.05	R
UMK105 CG221JV-F			CG	COG	220 p	±5%	1000	200	0.5±0.05	R
UMK105 CG271JV-F			CG	COG	270 p	±5%	1000	200	0.5±0.05	R
UMK105 CG331JV-F			CG	COG	330 р	±5%	1000	200	0.5 ± 0.05	R
UMK105 CG391JV-F			CG	COG	390 р	±5%	1000	200	0.5±0.05	R
UMK105 CG471JV-F			CG	COG	470 p	±5%	1000	200	0.5±0.05	R
UMK105 CG561JV-F		1	CG	COG	560 p	±5%	1000	200	0.5±0.05	R
UMK105 CG681JV-F		1	CG	COG	680 p	±5%	1000	200	0.5±0.05	R
UMK105 CG821JV-F		1	CG	COG	820 p	±5%	1000	200	0.5±0.05	R
UMK105 CG102JV-F			CG	COG	1000 p	±5%	1000	200	0.5±0.05	R

[Temperature Characteristic U Δ : U Δ /U2 Δ (-55~+125°C)] 0.5mm thickness(V)

Part number 1	Part number 2	Rated voltage [V]	Tempe		Capacitance [F]	Capacitance tolerance	Q (at 1MHz)	HTLT	Thickness*3 [mm]	Soldering R:Reflow
		[4]					min	Rated voltage x %		W:Wave
UMK105 UK0R5CV-F			UK	U2K	0.5 p	±0.25pF	410	200	0.5 ± 0.05	R
UMK105 UK010CV-F			UK	U2K	1 p	±0.25pF	420	200	0.5 ± 0.05	R
UMK105 UK1R5CV-F			UK	U2K	1.5 p	±0.25pF	430	200	0.5 ± 0.05	R
UMK105 UK020CV-F			UK	U2K	2 p	±0.25pF	440	200	0.5 ± 0.05	R
UMK105 UK030CV-F			UK	U2K	3 p	±0.25pF	460	200	0.5 ± 0.05	R
UMK105 UJ040CV-F			UJ	U2J	4 p	±0.25pF	480	200	0.5 ± 0.05	R
UMK105 UJ050CV-F			UJ	U2J	5 p	±0.25pF	500	200	0.5 ± 0.05	R
UMK105 UJ060DV-F			UJ	U2J	6 p	±0.5pF	520	200	0.5 ± 0.05	R
UMK105 UJ070DV-F			UJ	U2J	7 p	±0.5pF	540	200	0.5 ± 0.05	R
UMK105 UJ080DV-F			UJ	U2J	8 p	±0.5pF	560	200	0.5 ± 0.05	R
UMK105 UJ090DV-F			UJ	U2J	9 p	±0.5pF	580	200	0.5 ± 0.05	R
UMK105 UJ100DV-F			UJ	U2J	10 p	±0.5pF	600	200	0.5 ± 0.05	R
UMK105 UJ120JV-F			UJ	U2J	12 p	±5%	640	200	0.5 ± 0.05	R
UMK105 UJ150JV-F			UJ	U2J	15 p	±5%	700	200	0.5 ± 0.05	R
UMK105 UJ180JV-F		50	UJ	U2J	18 p	±5%	760	200	0.5 ± 0.05	R
UMK105 UJ220JV-F		30	UJ	U2J	22 p	±5%	840	200	0.5 ± 0.05	R
UMK105 UJ270JV-F			UJ	U2J	27 p	±5%	940	200	0.5 ± 0.05	R
UMK105 UJ330JV-F			UJ	U2J	33 p	±5%	1000	200	0.5 ± 0.05	R
UMK105 UJ390JV-F			UJ	U2J	39 p	±5%	1000	200	0.5 ± 0.05	R
UMK105 UJ470JV-F			UJ	U2J	47 p	±5%	1000	200	0.5 ± 0.05	R
UMK105 UJ560JV-F			UJ	U2J	56 p	±5%	1000	200	0.5 ± 0.05	R
UMK105 UJ680JV-F			UJ	U2J	68 p	±5%	1000	200	0.5 ± 0.05	R
UMK105 UJ820JV-F			UJ	U2J	82 p	±5%	1000	200	0.5 ± 0.05	R
UMK105 UJ101JV-F			UJ	U2J	100 p	±5%	1000	200	0.5 ± 0.05	R
UMK105 UJ121JV-F]	UJ	U2J	120 p	±5%	1000	200	0.5±0.05	R
UMK105 UJ151JV-F]	UJ	U2J	150 p	±5%	1000	200	0.5±0.05	R
UMK105 UJ181JV-F		1	UJ	U2J	180 p	±5%	1000	200	0.5±0.05	R
UMK105 UJ221JV-F		1	UJ	U2J	220 p	±5%	1000	200	0.5±0.05	R
UMK105 UJ271JV-F		1	UJ	U2J	270 p	±5%	1000	200	0.5±0.05	R
UMK105 UJ331JV-F		1	UJ	U2J	330 p	±5%	1000	200	0.5±0.05	R

[Temperature Characteristic $SL(-55\sim+125^{\circ}C)$] 0.5mm thickness(V)

Part number 1	Part number 1 Part number 2 Rated voltag				Capacitance			HTLT	Thickness*3 [mm]	Soldering R:Reflow
					[F]	<u> </u>	min	Rated voltage x %		W:Wave
UMK105 SL121JV-F			SL		120 p	±5%	1000	200	0.5±0.05	R
UMK105 SL151JV-F			SL		150 p	±5%	1000	200	0.5 ± 0.05	R
UMK105 SL181JV-F		50	SL		180 p	±5%	1000	200	0.5±0.05	R
UMK105 SL221JV-F		30	SL		220 p	±5%	1000	200	0.5±0.05	R
UMK105 SL271JV-F			SL		270 p	±5%	1000	200	0.5±0.05	R
UMK105 SL331JV-F			SL		330 р	±5%	1000	200	0.5 ± 0.05	R

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our product specification sheets. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/).

Multilayer Ceramic Capacitors

■PACKAGING

1 Minimum Quantity

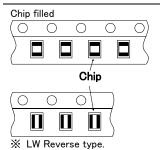
Taped package	TILL		0, 1, 1	F 3
Type(EIA)	Thick mm	code	Paper tape	uantity [pcs] Embossed tape
□MK021(008004)	0.125	K	- парет саре	50000
□VS021(008004)	0.123	IX		30000
☐MK042(01005)	0.2	C, D	_	40000
□VS042(01005)	0.2	С	_	40000
☐MK063(0201)	0.3	P,T	15000	_
□WK105(0204) ※	0.3	Р	10000	_
	0.13	Н	_	20000
DM(105(0400)	0.18	E	_	15000
☐MK105(0402) ☐MF105(0402)	0.2	С	20000	_
MF 105(0402)	0.3	Р	15000	_
	0.5	V	10000	_
□VK105(0402)	0.5	W	10000	_
□MK107(0603)	0.45	K	4000	_
□WK107(0306) ※	0.5	V	_	4000
□MF107(0603)	0.8	Α	4000	_
□VS107(0603)	0.7	С	4000	_
□MJ107(0603)	0.8	Α	3000	3000
□MK212(0805)	0.45	K	4000	
□WK212(0508) ※	0.85	D	4000	_
□MF212(0805)	1.25	G	_	3000
□VS212(0805)	0.85	D	4000	_
	0.85	D	4000	_
□MJ212(0805)	1.25	G	_	2000
	0.85	D	4000	_
□MK316(1206)	1.15	F	_	3000
□MF316(1206)	1.6	L	_	2000
	1.15	F	_	3000
□MJ316(1206)	1.6	L	_	2000
	0.85	D		
	1.15	F	1	
☐MK325(1210)	1.9	N	1 -	2000
□MF325(1210)	2.0max.	Y	1	
	2.5	M	_	1000
[] 1 1005(1015)	1.9	N	_	2000
□MJ325(1210)	2.5	М	_	500(T), 1000(P)
□MK432(1812)	2.5	М	_	500

Note:

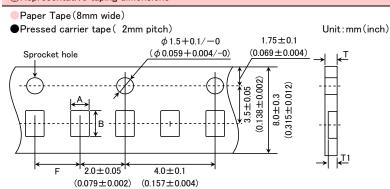
K LW Reverse type.

**No bottom tape for pressed carrier tape Card board carrier tape Top tape Base tape Sprocket hole Chip cavity Base tape Chip cavity

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).



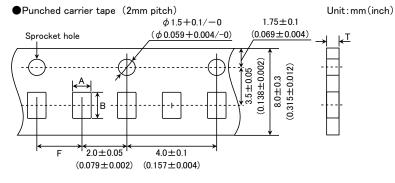
3 Representative taping dimensions



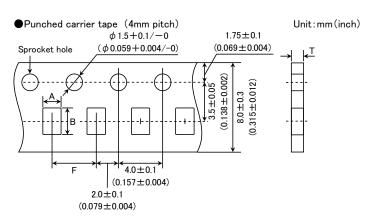
Type(EIA)	Chip	Cavity	Insertion Pitch	Tape Thickness		
Type(EIA)	Α	В	F	Т	T1	
□MK063(0201)	0.37	0.67		0.45max.	0.42max.	
□WK105(0204) ※			2.0±0.05	0.45max.	0.42max.	
□MK105(0402) (*1 C)	0.65	1.15	2.0±0.05	0.4max.	0.3max.	
□MK105(0402) (*1 P)				0.45max.	0.42max.	

Note *1 Thickness, C:0.2mm ,P:0.3mm. * LW Reverse type.

Unit:mm



Type(EIA)	Chip	Cavity	Insertion Pitch	Tape Thickness
Type(EIA)	Α	В	F	Т
☐MK105 (0402)				
☐MF105 (0402)	0.65	1.15	2.0 ± 0.05	0.8max.
□VK105 (0402)				
	•			Unit:mm

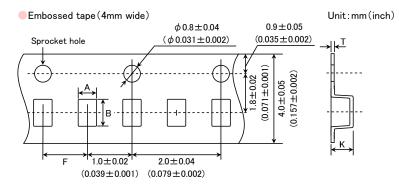


This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

Type(EIA)	Chip (Cavity	Insertion Pitch	Tape Thickness	
Type(EIA)	A B		F	Т	
☐MK107(0603)					
□WK107(0306) ※	1.0	1.8		1.1max.	
☐MF107(0603)			40+01		
☐MK212(0805)	1.65	0.4	4.0±0.1		
□WK212(0508) ※	1.65	2.4		1.1max.	
☐MK316(1206)	2.0	3.6			

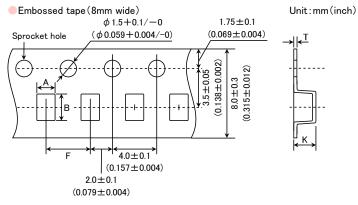
Note: Taping size might be different depending on the size of the product. X LW Reverse type.

Unit:mm



Type(EIA)	Chip (Cavity	Insertion Pitch	Tape Thickness		
Type(EIA)	Α	В	F	K	Т	
☐MK021(008004)	0.135	0.27				
□VS021(008004)	0.135	0.27	101000	0.5max.	0.25max.	
☐MK042(01005)	0.23	0.40	1.0±0.02		0.25max.	
□VS042(01005)	0.23	0.43				

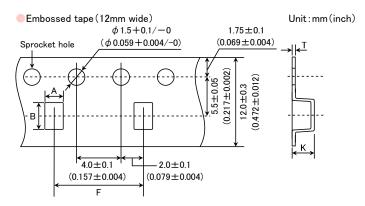
Unit:mm



Type(EIA)	Chip (Cavity	Insertion Pitch	Tape Thickness		
Type(EIA)	Α	В	F	K	Т	
☐MK105(0402)	0.6	1.1	2.0±0.1	0.6max	0.2±0.1	
□WK107(0306) ※	1.0	1.8		1.3max.	0.25±0.1	
☐MK212(0805) ☐MF212(0805)	1.65	2.4			0.6max.	
☐MK316(1206) ☐MF316(1206)	2.0	3.6	4.0±0.1	3.4max.		
☐MK325(1210) ☐MF325(1210)	2.8	3.6]			

Note: ※ LW Reverse type. Unit:mm

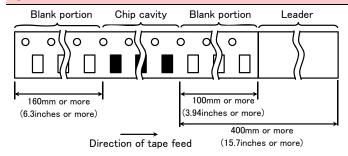
This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).



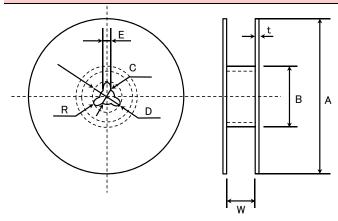
Type(EIA)	Chip (Cavity	Insertion Pitch	Tape Thickness		
Type(EIA)	Α	В	F	K	Т	
☐MK325(1210)	3.1	4.0	8.0±0.1	4.0max.	0.6max.	
☐MK432(1812)	3.7	4.9	8.0±0.1	4.0max.	0.6max.	

Unit:mm

4 Trailer and Leader



⑤Reel size



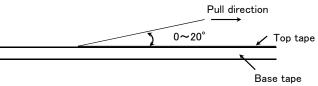
Α	В	С	D	E	R
ϕ 178 ± 2.0	<i>ф</i> 50min.	ϕ 13.0 \pm 0.2	ϕ 21.0 ± 0.8	2.0±0.5	1.0

	T	W
4mm wide tape	1.5max.	5±1.0
8mm wide tape	2.5max.	10±1.5
12mm wide tape	2.5max.	14±1.5

Unit:mm

6Top Tape Strength

The top tape requires a peel-off force of 0.1 to 0.7N in the direction of the arrow as illustrated below.



This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

Multilayer Ceramic Capacitors

■RELIABILITY DATA

	Temperature	Standard	l					
Compensating(Class1)	High Frequency Type	_55 to ∃	−55 to +125°C					
				Specification	Temperature Range			
				В	−25 to +85°C			
Specified			BJ	X5R	−55 to +85°C			
√alue		`	B7	X7R	−55 to +125°C			
	High Permittivity (Class2)	C6	X6S	−55 to +105°C			
			C7	X7S	−55 to +125°C			
			LD(※)	X5R	−55 to +85°C			
			Note: >	LD Low distortion hi	gh value multilayer ceramic capa			
	•							
. Storage Co	aditions							
Storage Ooi		Standard						
	Temperature		−55 to +	−55 to +125°C				
Compensating(Class1)	High Frequency Type							
				Specification	Temperature Range			
C:E1			BJ	В	−25 to +85°C			
Specified Value				X5R	−55 to +85°C			
value	High Permittivity (Class2)	B7	X7R	−55 to +125°C			
	,g	,	C6	X6S	−55 to +105°C			
			C7	X7S	−55 to +125°C			
		LD(X)	X5R	−55 to +85°C				
			Note: •	LD Low distortion hi	gh value multilayer ceramic capa			
3. Rated Volta	ge							
	Temperature	Standard	50VDC, 25	SVDC, 16VDC				
Specified Value	Compensating(Class1)	High Frequency Type	50VDC, 25	SVDC, 16VDC				
	High Permittivity (Class2)	50VDC, 35	5VDC, 25VDC, 16VDC	C, 10VDC, 6.3VDC, 4VDC, 2.5VD			
I. Withstandin	g Voltage(Between termina	ls)						

4. Withstanding	Voltage (Between terminal	s)					
0 15 1	Temperature	Standard					
Specified Value	Compensating(Class1)	High Frequency Type		No breakdown o	No breakdown or damage		
- Value	High Permittivity (Class2)						
- .			Cla	iss 1	Class 2		
Test Methods and	Applied voltage Rated		Rated v	Rated voltage × 3 Rated voltage × 2.5			
Remarks	Duration			1 to 5			
Remarks	Charge/discharge currer	nt		50mA			

5. Insulation Re	5. Insulation Resistance					
	Temperature	Standard	10000 MΩmin.			
Value	Compensating(Class1)	High Frequency Type	וווווו.			
	High Permittivity (Class2) Note 1		C ≤ 0.047 μ F : 10000 M Ω min. C>0.047 μ F : 500M Ω• μ F			
Test	Applied voltage	: Rated voltage				
Methods and	Duration	: 60±5 sec.				
Remarks	Charge/discharge current	: 50mA max.				

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

6. Capacitance (Tolerance)								
Temperature Specified Compensating Class	Temperature Compensating(Class1)	Standard	C U SL	0.2pF≦C≦5pF 0.2pF≦C≦10pF C>10pF	: ±0.25pF : ±0.5pF : ±5% or ±10%			
Value		High Frequency Type	CG	0.2pF≦C≦2pF C>2pF	: ±0.1pF : ±5%			
	High Permittivity (Class2))	$\pm 10\%$ or $\pm 20\%$					
			Class 1		Class 2			
- .	Standa		t t	High Frequency Type	C≦10 <i>µ</i> F	C>10 µF		
Test	Preconditioning		None		Thermal treatment (at 150°C for 1hr) Note 2			
Methods and	Measuring frequency		1MHz±10%		1kHz±10%	120±10Hz		
Remarks	Measuring voltage Nte		0.5 to	5Vrms	1±0.2Vrms	0.5±0.1Vrms		
	Bias application				None			

Specified Value	Temperature		Standard	andard C<30pF : Q≥400+20C C≥30pF : Q≥1000 (C:Nominal capacitance)			
	Compensating(Class1)	High Frequency Type		Refer	to detailed specification		
	High Permittivity (Class2) Note 1			BJ, B7, C6, C7: 2.5% max.			
				Class 1		Class 2	
	1		Standard		High Frequency Type	C≦10 <i>µ</i> F	C>10 µF
	Preconditioning	Preconditioning		None		Thermal treatment (at 150°C for 1hr) Note 2	
Test	Measuring frequency		1MHz±10%		1GHz	1kHz±10%	120±10Hz
Methods and	Measuring voltage Note		0.5 to 5Vrms			1±0.2Vrms	0.5±0.1Vrms
Remarks	Bias application		None				
	High Frequency Type						
	Measuring equipment	: HP	4291A				
	Measuring jig : HP16192A						

8. Temperature Chara	cteristic (Without vo	ltage application)						
			Tem	perature Charac	cteristic [ppm/°	C]	Tolerance [ppm/°C]	
			C□:	0	CG		G: ±30	
	perature	Standard	U□ :	— 750	UJ, UK		J: ±120 K: ±250	
Com	pensating(Class1)		SL :	+350 to −100	0			
		High Frequency Type	Temperature Charact		teristic [ppm/°	C]	Tolerance [ppm/°C]	
			C□:	0	CG		G: ±30	
Specified Value	High Permittivity (Class2)			Specification	Capacitance	Referer	Temperature Rang	
value				ороспоссоп	change	tempera	ture	
				В	±10%	20°C	-25 to +85°C	
				X5R	±15%	25°C	−55 to +85°C	
High				X7R	±15%	25°C	-55 to +125℃	
			C6	XS	±22%	25°C	-55 to +105°C	
	Class 1			X7S	±22%	25°C	-55 to +125℃	
				X5R	±15%	25°C	-55 to +85°C	
				LD Low disto	rtion high value i	multilaver c	ceramic capacitor	

Class 1

Capacitance at 20° C and 85° C shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation.

$$\frac{(C_{85}-C_{20})}{C_{20}\times\Delta T} \times 10^{6} (ppm/^{\circ}C) \qquad \Delta T = 65$$

Test Methods and Remarks Canadita

Capacitance at each step shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation.

Step	В	X5R, X7R, X6S, X7S				
1	Minimum operating temperature					
2	20°C	25°C				
3	Maximum operating temperature					

 $\frac{(C-C_2)}{C_2}$ × 100 (%) $\frac{C}{C_2}$: Capacitance in Step 1 or Step 3 $\frac{C_2}{C_2}$: Capacitance in Step 2

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

9. Deflection						
Temperature Compensating(Class1) Value	Temperature	Standard	Appearance Capacitance change	: No abnormality : Within $\pm 5\%$ or ± 0.5 pF, whichever is larger.		
	High Frequency Typ	e Appearance Capacitance change	: No abnormality : Within \pm 0.5 pF			
	High Permittivity	(Class2)	Appearance Capacitance change	Appearance : No abnormality Capacitance change : Within ±12.5%		
		Multilayor Car	amic Capacitors	20		
		021, 042, 063, *105 Type	The other types			
Test	Board		resin substrate	Board R-230 Warp		
Methods and	Thickness	0.8mm	1.6mm			
Remarks	Warp	1	mm	45±2 45±2 1		
rtomartto	Duration	10	sec.	 		
		*105 Type thickness, C: 0.	2mm ,P: 0.3mm.	(Unit: mm)		
				Capacitance measurement shall be conducted		
				with the board bent		

10. Body Stren	10. Body Strength					
0 10 1	Temperature	Standard	1			
Specified Value	Compensating(Class1)	High Frequency Type	No mechanical damage.			
value	High Permittivity (Class2))				
Test Methods and Remarks	High Frequency 105Type Applied force : 5N Duraton : 10 sec.	Pres ← A →	Pressing Jig Chip A			

11. Adhesive S	trength of Terminal Ele	ctrodes				
	Temperature	Standard				
Specified Value	Compensating(Class	1) High Frequency Typ	e No terminal separati	No terminal separation or its indication.		
Value	High Permittivity (C	lass2)				
		Multilayer Cera	mic Capacitors	Hooked jig		
Test		021, 042, 063 Type	105 Type or more			
Methods and	Applied force	2N	5N	R=05 🖟 Board		
Remarks	Duration	30±5	sec.] ←Chip		
				Chip Chip		

12. Solderability	12. Solderability					
	Temperature	Standard				
Specified Value	Compensating(Class1)	High Frequency Type At least 95% of terminal electrode is covered b		by new solder.		
Value	High Permittivity (Class2))				
		Eutectic s		Lead-free solder		
Test Methods and	Solder type	H60A or H	63A	Sn-3.0Ag-0.5Cu		
Remarks	Solder temperature	230±5°	С	245±3°C		
Remarks	Duration		4±1 sec.			

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

	to Soldering		T		
Specified Value	Temperature	Standard	Appearance Capacitance cha Q Insulation resista Withstanding vol	: Initial value nce : Initial value	±0.25pF, whichever is larger. ⇒ : No abnormality
	Compensating(Class1	High Frequency Type	Appearance Capacitance cha Q Insulation resista Withstanding vol	: Initial value nce : Initial value	:) : No abnormality
	High Permittivity (Class2) Note 1		Appearance Capacitance cha Dissipation facto Insulation resista Withstanding vol	: Initial value	s): No abnormality
			Class 1		
		021, 042, 063 Type		105 Type	<u>_</u>
	Preconditioning		None		_
	Preheating	150°C, 1 to 2 min.		to 100°C, 2 to 5 min. O to 200°C, 2 to 5 min.	
	Solder temp.		270±5°C		7
	Duration		3±0.5 sec.		
est	Recovery	6 to 24 hrs	Standard condit	on) Note 5	
Methods and Remarks				Class 2	
		021, 042, 063 Type		105, 107, 212 Type	316, 325, 432 Type
	Preconditioning		Thermal treat	ment (at 150°C for 1 hr) I	Note 2
	Preheating	150°C, 1 to 2 min.		to 100°C, 2 to 5 min. O to 200°C, 2 to 5 min.	80 to 100°C, 5 to 10 min. 150 to 200°C, 5 to 10 min.
	Solder temp.		•	270±5°C	•
	Duration			3±0.5 sec.	
	Recovery		24±2 hrs	(Standard condition) Note	5

14. Temperatur	re Cycle (Thermal Shock)						
Specified Value	Temperature	Standard		Capacitance change : Q : Insulation resistance :	No abnormality Within ±2.5% or ±0.25 Initial value Initial value (between terminals): N	· ·	
	Compensating(Class1)	High Frequency	Туре	Capacitance change : Q : Insulation resistance :	No abnormality Within ±0.25pF Initial value Initial value (between terminals): N	o abnormality	
	High Permittivity (Class2) Note 1			Capacitance change : Dissipation factor : Insulation resistance :	No abnormality Within ±7.5% Initial value Initial value (between terminals): N	o abnormality	
			(Class 1		Class 2	
	Preconditioning			None	Thermal trea	tment (at 150°C for 1 hr) Note 2	
Test Methods and Remarks	1 cycle		Step 1 2 3 4	Minimum operatir Normal tem Maximum operatir	${ m crature}({ m ^{\circ}C})$ ${ m Time}({ m min.})$ ${ m rating temperature}$ ${ m 30\pm3}$ ${ m temperature}$ ${ m 2 to 3}$ ${ m rating temperature}$ ${ m 30\pm3}$ ${ m temperature}$ ${ m 2 to 3}$		
	Number of cycles			Į.	5 times		1
	Recovery	6 to 24 hrs	(Stan	dard condition) Note 5	24±2 hrs (5	Standard condition)Note 5	1

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

15. Humidity (Steady State)					
	Temperature Compensating(Class1	Standard	Standard Capacitance change : Wit Q : C < 10 C		No abnormality Within $\pm 5\%$ or ± 0.5 pF, whichever is larger. $C < 10$ pF : $Q \ge 200 + 10$ C $10 \le C < 30$ pF : $Q \ge 275 + 2.5$ C $C \ge 30$ pF: $Q \ge 350$ ($C : Nominal \ capacitance$) 1000 M Ω min.	
Specified Value		High Frequency Type	Capacitance change	: Within	No abnormality Within ±0.5pF, 1000 MΩmin.	
	High Permittivity (Class2) Note 1		Capacitance change Dissipation factor	: Within : 5.0% n	onormality n \pm 12.5% max. $\Omega ot\! \! \! \! \! \! \! \! \! \! \! \! \! \! \! \! \! \! \! $	
		Cla	Class 1		Class 2	
		Standard	High Frequency Type		All items	
Test	Preconditioning	N	lone		Thermal treatment(at 150°C for 1 hr) Note 2	
Methods and	Temperature	40±2°C	60±2°C		40±2°C	
Remarks	Humidity	90 to	95%RH		90 to 95%RH	
	Duration	500+2	4/-0 hrs		500+24/-0 hrs	
	Recovery	6 to 24 hrs (Stand	ard condition)Note 5		24±2 hrs(Standard condition)Note 5	

16. Humidity Lo	pading					
Specified Value	Temperature	Standard	$C \geqq 30 pF : Q \geqq 200 (C : Nominal \ capacitance)$ Insulation resistance $: 500 \ M\Omega \ min.$ Appearance $: No \ abnormality$ Capacitance change $: C \leqq 2pF : Within \ \pm 0.4 \ pF$		hin ±7.5% or ±0.75pF, whichever is larger. ≲30pF:Q≧100+10C/3 ≧30pF:Q≧200 (C:Nominal capacitance)	
	Compensating (Class1)	High Frequency Type			2pF:Within ±0.4 pF 2pF:Within ±0.75 pF (C:Nominal capacitance)	
	High Permittivity (Class2	Appearance Capacitance change Dissipation factor Insulation resistance	: Wit	abnormality hin \pm 12.5% % max. M $\Omega\mu$ F or 500 M Ω whichever is smaller.		
			Class 1		Class 2	
		Standard	High Frequency Ty	ре	All items	
	Preconditioning		None		Voltage treatment (Rated voltage are applied for 1 hour at 40°C) Note 3	
Test	Temperature	40±2°C	60±2°C		40±2°C	
Methods and	Humidity	90 t	to 95%RH		90 to 95%RH	
Remarks	Duration	500+	24/-0 hrs		500+24/-0 hrs	
	Applied voltage	Rate	ed voltage		Rated voltage	
	Charge/discharge current	50r	mA max.		50mA max.	
	Recovery	6 to 24 hrs (Stan	dard condition)Note 5		24±2 hrs(Standard condition) Note 5	

17. High Tempe	erature Loading					
Specified Value	Temperature Compensating(Class1)	Standard Appearance Capacitance change Q Insulation resistance		: $C < 10pF$: $Q \ge 200 + 10C$ $10 \le C < 30pF$: $Q \ge 275 + 2.5C$ $C \ge 30pF$: $Q \ge 350(C$: Nominal capacitance)		
		High Frequency Type	Appearance : No abnormality cquency Type Capacitance change : Within $\pm 3\%$ or ± 0.3 pF, whichever is larger. Insulation resistance : $1000 \text{ M}\Omega$ min.			
	High Permittivity (Class2) Note 1	Appearance Capacitance change Dissipation factor Insulation resistance	: 5.0% max.		
		Clas	s 1	Class 2		
		Standard F	High Frequency Type	BJ, LD(<u>*</u>) C6 B7, C7		
	Preconditioning	None		Voltage treatment (Twice the rated voltage shall be applied for 1 hour at 85°C, 105°C or 125°C) Note 3, 4		
Test	Temperature	Maximum operatir	ng temperature	Maximum operating temperature		
Methods and	Duration	1000+48	/-0 hrs	1000+48/-0 hrs	1	
Remarks	Applied voltage	Rated voltage	×2 Note 4	Rated voltage × 2 Note 4	1	
Remarks	Charge/discharge current	50mA max.		50mA max.		
	Recovery	6 to 24hr (Standard	condition) Note 5	24±2 hrs(Standard condition)Note 5		
			Note:	: ※LD Low distortion high value multilayer ceramic capacitor	-	

Note 1 The figures indicate typical specifications. Please refer to individual specifications in detail.

- Note 2 Thermal treatment : Initial value shall be measured after test sample is heat-treated at $150 \pm 0/-10^{\circ}$ C for an hour and kept at room temperature for 24 ± 2 hours.
- Note 3 Voltage treatment: Initial value shall be measured after test sample is voltage-treated for an hour at both the temperature and voltage specified in the test conditions, and kept at room temperature for 24±2hours.
- Note 4 150% of rated voltage is applicable to some items. Please refer to their specifications for further information.
- Note 5 Standard condition: Temperature: 5 to 35°C, Relative humidity: 45 to 85 % RH, Air pressure: 86 to 106kPa When there are questions concerning measurement results, in order to provide correlation data, the test shall be conducted under the following condition.

Temperature: 20±2°C, Relative humidity: 60 to 70 % RH, Air pressure: 86 to 106kPa Unless otherwise specified, all the tests are conducted under the "standard condition".

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

Precautions on the use of Multilayer Ceramic Capacitors

PRECAUTIONS

1. Circuit Design

- ◆Verification of operating environment, electrical rating and performance
 - 1. A malfunction of equipment in fields such as medical, aerospace, nuclear control, etc. may cause serious harm to human life or have severe social ramifications.

Therefore, any capacitors to be used in such equipment may require higher safety and reliability, and shall be clearly differentiated from them used in general purpose applications.

Precautions

- ◆Operating Voltage (Verification of Rated voltage)
- 1. The operating voltage for capacitors must always be their rated voltage or less.
 - If an AC voltage is loaded on a DC voltage, the sum of the two peak voltages shall be the rated voltage or less.
 - For a circuit where an AC or a pulse voltage may be used, the sum of their peak voltages shall also be the rated voltage or less.
- 2. Even if an applied voltage is the rated voltage or less reliability of capacitors may be deteriorated in case that either a high frequency AC voltage or a pulse voltage having rapid rise time is used in a circuit.

2. PCB Design

Precautions

- ◆Pattern configurations (Design of Land-patterns)
- 1. When capacitors are mounted on PCBs, the amount of solder used (size of fillet) can directly affect the capacitor performance. Therefore, the following items must be carefully considered in the design of land patterns:
 - (1) Excessive solder applied can cause mechanical stresses which lead to chip breaking or cracking. Therefore, please consider appropriate land-patterns for proper amount of solder.
 - (2) When more than one component are jointly soldered onto the same land, each component's soldering point shall be separated by solder-resist.
- ◆Pattern configurations (Capacitor layout on PCBs)

After capacitors are mounted on boards, they can be subjected to mechanical stresses in subsequent manufacturing processes (PCB cutting, board inspection, mounting of additional parts, assembly into the chassis, wave soldering of the boards, etc.). For this reason, land pattern configurations and positions of capacitors shall be carefully considered to minimize stresses.

◆Pattern configurations (Design of Land-patterns)

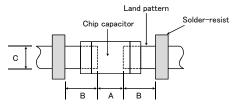
The following diagrams and tables show some examples of recommended land patterns to prevent excessive solder amounts.

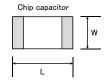
- (1) Recommended land dimensions for typical chip capacitors
- Multilayer Ceramic Capacitors : Recommended land dimensions (unit: mm)

Wave-soldering

Type		107 212		316	325	
C:		1.6 2.0		3.2	3.2	
Size		0.8	1.25	1.6	2.5	
A	١	0.8 to 1.0	1.0 to 1.4	1.8 to 2.5	1.8 to 2.5	
В		0.5 to 0.8	0.8 to 1.5	0.8 to 1.7	0.8 to 1.7	
С		0.6 to 0.8	0.9 to 1.2	1.2 to 1.6	1.8 to 2.5	

Land patterns for PCBs





Technical considerations

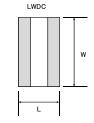
Reflow-soldering

110	IIOW 3	Solucing								
Ту	фе	021	042	063	105	107	212	316	325	432
Size	L	0.25	0.4	0.6	1.0	1.6	2.0	3.2	3.2	4.5
Size	W	0.125	0.2	0.3	0.5	0.8	1.25	1.6	2.5	3.2
/	4	0.095~0.135	0.15~0.25	0.20~0.30	0.45~0.55	0.8~1.0	0.8~1.2	1.8~2.5	1.8~2.5	2.5~3.5
E	3	0.085~0.125	0.15~0.20	0.20~0.30	0.40~0.50	0.6~0.8	0.8~1.2	1.0~1.5	1.0~1.5	1.5~1.8
()	0.110~0.150	0.15~0.30	0.25~0.40	0.45~0.55	0.6~0.8	0.9~1.6	1.2~2.0	1.8~3.2	2.3~3.5

 $Note: Recommended \ land \ size \ might be \ different \ according \ to \ the \ allowance \ of \ the \ size \ of \ the \ product.$

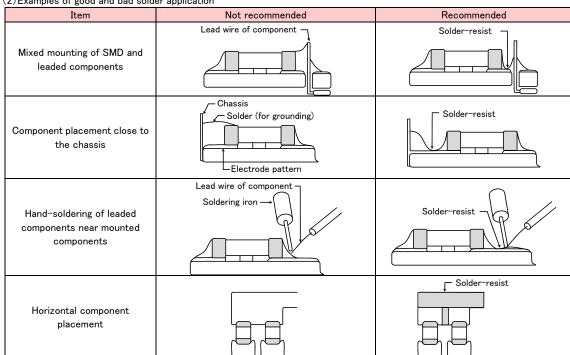
●LWDC: Recommended land dimensions for reflow-soldering (unit: mm)

Type		105	107	212
C:	L	0.52	0.8	1.25
Size		1.0	1.6	2.0
-	4	0.18~0.22	0.25~0.3	0.5~0.7
В		0.2~0.25	0.3~0.4	0.4~0.5
С		0.9~1.1	1.5~1.7	1.9~2.1



This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

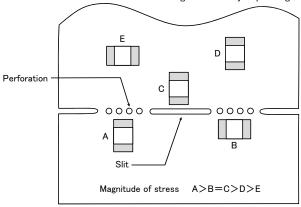
(2) Examples of good and bad solder application



- ◆Pattern configurations (Capacitor layout on PCBs)
 - 1-1. The following is examples of good and bad capacitor layouts; capacitors shall be located to minimize any possible mechanical stresses from board warp or deflection.

Items	Not recommended	Recommended
Deflection of board		Place the product at a right angle to the direction of the anticipated mechanical stress.

1-2. The amount of mechanical stresses given will vary depending on capacitor layout. Please refer to diagram below.



1-3. When PCB is split, the amount of mechanical stress on the capacitors can vary according to the method used. The following methods are listed in order from least stressful to most stressful: push-back, slit, V-grooving, and perforation. Thus, please consider the PCB, split methods as well as chip location.

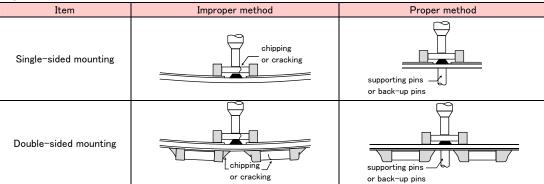
3. Mounting

- ◆Adjustment of mounting machine
 - 1. When capacitors are mounted on PCB, excessive impact load shall not be imposed on them.
 - 2. Maintenance and inspection of mounting machines shall be conducted periodically.
- ◆Selection of Adhesives Precautions
 - 1. When chips are attached on PCBs with adhesives prior to soldering, it may cause capacitor characteristics degradation unless the following factors are appropriately checked: size of land patterns, type of adhesive, amount applied, hardening temperature and hardening period. Therefore, please contact us for further information.

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/) .

◆Adjustment of mounting machine

- 1. When the bottom dead center of a pick-up nozzle is too low, excessive force is imposed on capacitors and causes damages. To avoid this, the following points shall be considerable.
 - (1) The bottom dead center of the pick-up nozzle shall be adjusted to the surface level of PCB without the board deflection.
 - (2) The pressure of nozzle shall be adjusted between 1 and 3 N static loads.
 - (3) To reduce the amount of deflection of the board caused by impact of the pick-up nozzle, supporting pins or back-up pins shall be used on the other side of the PCB. The following diagrams show some typical examples of good and bad pick-up nozzle placement:



Technical considerations

2. As the alignment pin is worn out, adjustment of the nozzle height can cause chipping or cracking of capacitors because of mechanical impact on the capacitors.

To avoid this, the monitoring of the width between the alignment pins in the stopped position, maintenance, check and replacement of the pin shall be conducted periodically.

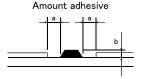
◆Selection of Adhesives

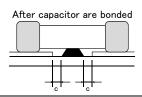
Some adhesives may cause IR deterioration. The different shrinkage percentage of between the adhesive and the capacitors may result in stresses on the capacitors and lead to cracking. Moreover, too little or too much adhesive applied to the board may adversely affect components. Therefore, the following precautions shall be noted in the application of adhesives.

- (1) Required adhesive characteristics
 - a. The adhesive shall be strong enough to hold parts on the board during the mounting & solder process.
 - b. The adhesive shall have sufficient strength at high temperatures.
 - c. The adhesive shall have good coating and thickness consistency.
 - d. The adhesive shall be used during its prescribed shelf life.
 - e. The adhesive shall harden rapidly.
 - f. The adhesive shall have corrosion resistance.
 - g. The adhesive shall have excellent insulation characteristics.
 - h. The adhesive shall have no emission of toxic gasses and no effect on the human body.
- (2) The recommended amount of adhesives is as follows;

[Recommended condition]

Figure	212/316 case sizes as examples
а	0.3mm min
b	100 to 120 μm
С	Adhesives shall not contact land





4. Soldering

Precautions

Technical

considerations

◆Selection of Flux

Since flux may have a significant effect on the performance of capacitors, it is necessary to verify the following conditions prior to use;

- (1) Flux used shall be less than or equal to 0.1 wt% (in Cl equivalent) of halogenated content. Flux having a strong acidity content shall not be applied.
- (2) When shall capacitors are soldered on boards, the amount of flux applied shall be controlled at the optimum level.
- (3) When water-soluble flux is used, special care shall be taken to properly clean the boards.

♦Soldering

Temperature, time, amount of solder, etc. shall be set in accordance with their recommended conditions.

Sn-Zn solder paste can adversely affect MLCC reliability.

Please contact us prior to usage of Sn-Zn solder.

◆Selection of Flux

- 1-1. When too much halogenated substance (Chlorine, etc.) content is used to activate flux, or highly acidic flux is used, it may lead to corrosion of terminal electrodes or degradation of insulation resistance on the surfaces of the capacitors.
- 1-2. Flux is used to increase solderability in wave soldering. However if too much flux is applied, a large amount of flux gas may be emitted and may adversely affect the solderability. To minimize the amount of flux applied, it is recommended to use a flux-bubbling system.
- 1-3. Since the residue of water-soluble flux is easily dissolved in moisture in the air, the residues on the surfaces of capacitors in high humidity conditions may cause a degradation of insulation resistance and reliability of the capacitors. Therefore, the cleaning methods and the capability of the machines used shall also be considered carefully when water-soluble flux is used.

meanous and the supu

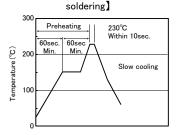
This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

♦Soldering

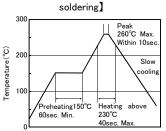
- · Ceramic chip capacitors are susceptible to thermal shock when exposed to rapid or concentrated heating or rapid cooling.
- · Therefore, the soldering must be conducted with great care so as to prevent malfunction of the components due to excessive thermal shock
- Preheating: Capacitors shall be preheated sufficiently, and the temperature difference between the capacitors and solder shall be within 130°C.
- · Cooling: The temperature difference between the capacitors and cleaning process shall not be greater than 100°C.

[Reflow soldering]

[Recommended conditions for eutectic

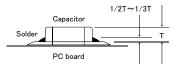


[Recommended condition for Pb-free



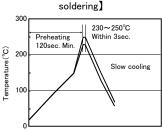
Caution

- 1The ideal condition is to have solder mass(fillet)controlled to 1/2 to 1/3 of the thickness of a capacitor.
- ②Because excessive dwell times can adversely affect solderability, soldering duration shall be kept as close to recommended times as possible. soldering for 2 times.

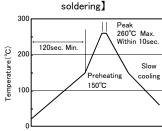


[Wave soldering]

[Recommended conditions for eutectic



[Recommended condition for Pb-free

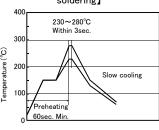


Caution

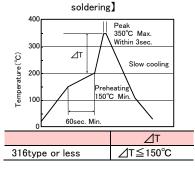
①Wave soldering must not be applied to capacitors designated as for reflow soldering only. soldering for 1 times.

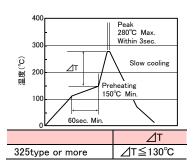
[Hand soldering]

【Recommended conditions for eutectic soldering】



[Recommended condition for Pb-free





Caution

- ①Use a 50W soldering iron with a maximum tip diameter of 1.0 mm.
- 2The soldering iron shall not directly touch capacitors. soldering for 1 times.

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

5. Cleaning Cleaning conditions 1. When PCBs are cleaned after capacitors mounting, please select the appropriate cleaning solution in accordance with the intended use Precautions of the cleaning. (e.g. to remove soldering flux or other materials from the production process.) 2. Cleaning condition shall be determined after it is verified by using actual cleaning machine that the cleaning process does not affect capacitor's characteristics. 1. The use of inappropriate cleaning solutions can cause foreign substances such as flux residue to adhere to capacitors or deteriorate their outer coating, resulting in a degradation of the capacitor's electrical properties (especially insulation resistance). 2. Inappropriate cleaning conditions (insufficient or excessive cleaning) may adversely affect the performance of the capacitors. In the case of ultrasonic cleaning, too much power output can cause excessive vibration of PCBs which may lead to the cracking of Technical considerations capacitors or the soldered portion, or decrease the terminal electrodes' strength. Therefore, the following conditions shall be carefully checked: 40 kHz or less Ultrasonic output: 20 W/Q or les Ultrasonic frequency: Ultrasonic washing period: 5 min. or less

6. Resin coating and mold

Precautions

1. With some type of resins, decomposition gas or chemical reaction vapor may remain inside the resin during the hardening period or while left under normal storage conditions resulting in the deterioration of the capacitor's performance.

2. When a resin's hardening temperature is higher than capacitor's operating temperature, the stresses generated by the excessive heat may lead to damage or destruction of capacitors.

The use of such resins, molding materials etc. is not recommended.

7. Handling

◆Splitting of PCB

Precautions

1. When PCBs are split after components mounting, care shall be taken so as not to give any stresses of deflection or twisting to the board.

2. Board separation shall not be done manually, but by using the appropriate devices.

◆Mechanical considerations

Be careful not to subject capacitors to excessive mechanical shocks.

- (1) If ceramic capacitors are dropped onto a floor or a hard surface, they shall not be used.
- (2) Please be careful that the mounted components do not come in contact with or bump against other boards or components.

8. Storage conditions

1. To maintain the solderability of terminal electrodes and to keep packaging materials in good condition, care must be taken to control temperature and humidity in the storage area. Humidity should especially be kept as low as possible.

Recommended conditions

Ambient temperature : Below 30°C

Humidity: Below 70% RH

Precautions

The ambient temperature must be kept below 40°C. Even under ideal storage conditions, solderability of capacitor is deteriorated as time passes, so capacitors shall be used within 6 months from the time of delivery.

- ·Ceramic chip capacitors shall be kept where no chlorine or sulfur exists in the air.
- 2. The capacitance values of high dielectric constant capacitors will gradually decrease with the passage of time, so care shall be taken to design circuits. Even if capacitance value decreases as time passes, it will get back to the initial value by a heat treatment at 150°C for

Technical considerations

If capacitors are stored in a high temperature and humidity environment, it might rapidly cause poor solderability due to terminal oxidation and quality loss of taping/packaging materials. For this reason, capacitors shall be used within 6 months from the time of delivery. If exceeding the above period, please check solderability before using the capacitors.

**RCR-2335B(Safety Application Guide for fixed ceramic capacitors for use in electronic equipment) is published by JEITA. Please check the guide regarding precautions for deflection test, soldering by spot heat, and so on.

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/) .

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Taiyo Yuden:

```
TMK316ABJ106KD-T LMK042B7101KC-FW LMK042B7101MC-FW LMK042B7102KC-FW LMK042B7102MC-FW
LMK042B7151KC-FW LMK042B7151MC-FW LMK042B7221KC-FW LMK042B7221MC-FW LMK042B7331KC-FW
LMK042B7331MC-FW LMK042B7471KC-FW LMK042B7471MC-FW LMK042B7681KC-FW LMK042B7681MC-FW
LMK042BJ101KC-FW LMK042BJ102KC-FW LMK042BJ103KC-FW LMK042BJ103MC-FW LMK042BJ221KC-FW
LMK042BJ471KC-FW LMK063BJ103KP-F LMK063BJ103MP-F LMK063BJ104KP-F LMK063BJ104MP-F
LMK063BJ152KP-F LMK063BJ222KP-F LMK063BJ222MP-F LMK063BJ223KP-F LMK063BJ223MP-F
LMK063BJ224MP-F LMK063BJ472KP-F LMK063BJ472MP-F LMK063BJ473KP-F LMK063C6273KP-F
LMK063C6273MP-F LMK063C6473MP-F LMK105B7104KV-F LMK105B7223KV-F LMK105B7333KV-F
LMK105B7473KV-F LMK105BJ104KC-F LMK105BJ104KV-F LMK105BJ104MV-F LMK105BJ105KV-F
LMK105BJ105MV-F LMK105BJ224KV-F LMK105BJ225MV-F LMK105BJ474KV-F LMK105BJ683KV-F
LMK105BJ683MV-F LMK105BJ823MV-F LMK105F223ZV-F LMK105F224ZV-F LMK105F473ZV-F
LMK105SD332JV-F LMK105SD332KV-F LMK105SD392JV-F LMK105SD392KV-F LMK105SD472JV-F
LMK105SD472KV-F LMK107B7105KA-T LMK107B7105MA-T LMK107B7154KA-T LMK107B7154MA-T
LMK107B7224KA-T LMK107B7224MA-T LMK107B7225KA-T LMK107B7334KA-T LMK107B7334MA-T
LMK107B7474KA-T LMK107B7474MA-T LMK107BJ105KA-T LMK107BJ105KK-T LMK107BJ105MA-T
LMK107BJ105MK-T LMK107BJ106MALTD LMK107BJ225KA-T LMK107BJ225MA-T LMK107BJ335KA-T
LMK107BJ475KA-T LMK107BJ684KA-T LMK107BJ684MA-T LMK107F105ZA-T LMK107F225ZA-T
LMK107SD123JA-T LMK107SD123KA-T LMK107SD153JA-T LMK107SD153KA-T LMK107SD183JA-T
LMK107SD183KA-T LMK107SD223JA-T LMK107SD223KA-T LMK212B7105KD-T LMK212B7105KG-T
LMK212B7105MD-T LMK212B7105MG-T LMK212B7106KG-TD LMK212B7225KD-T LMK212B7225KG-T
```